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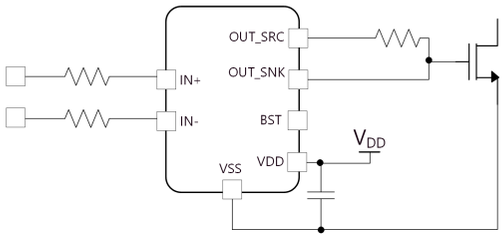
1EDN71x6U EiceDRIVER™

200 V high-side TDI gate driver IC for GaN SG HEMTs and MOSFETs

Features

- Optimized for driving GaN SG HEMTs and Si MOSFETs
- Fully differential logic input circuitry to avoid false triggering in low-side or high-side operation
- High common-mode input voltage range (CMR) up to ± 200 V for high side operation
- High immunity to common-mode voltage transitions (100 V/ns) for robust operation during fast switching
- Compatible with 3.3 V or 5 V input logic
- Four driving strength variants to optimize switching speed without external gate resistors - up to 2 A source/sink current capability
- Active bootstrap clamp to avoid bootstrap capacitor overcharging during dead-time
- Active Miller clamp with 5 A sink capability to avoid induced turn-on
- Qualified for industrial applications according to the relevant tests of JEDEC47/20/22





Description

The 1EDN71x6U is a single-channel gate-driver IC optimized for driving Infineon CoolGaN™ Schottky Gate HEMTs, as well as other GaN SG HEMTs and Si MOSFETs. This gate driver includes several key features that enable a high-performance system design with GaN SG HEMTs, including Truly Differential Input, four driving strength options, active Miller clamp, and bootstrap voltage clamp.

Potential applications

- Single channel:
  - Synchronous rectifier
  - Class-E resonant wireless power
- Half-bridge (2 x 1EDN71x6U):
  - DC-DC converter
  - BLDC/PMSM motor drive
  - Class-D audio amplifier
  - Class-D resonant wireless power

Product portfolio

Part number	Peak source/sink current	Input pulse blanking time	Package
1EDN7116U	2.0 A	20 ns	PG-TSNP-7
1EDN7126U	1.5 A	40 ns	PG-TSNP-7
1EDN7136U	1.0 A	60 ns	PG-TSNP-7
1EDN7146U	0.5 A	80 ns	PG-TSNP-7

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1 Pin configuration and description

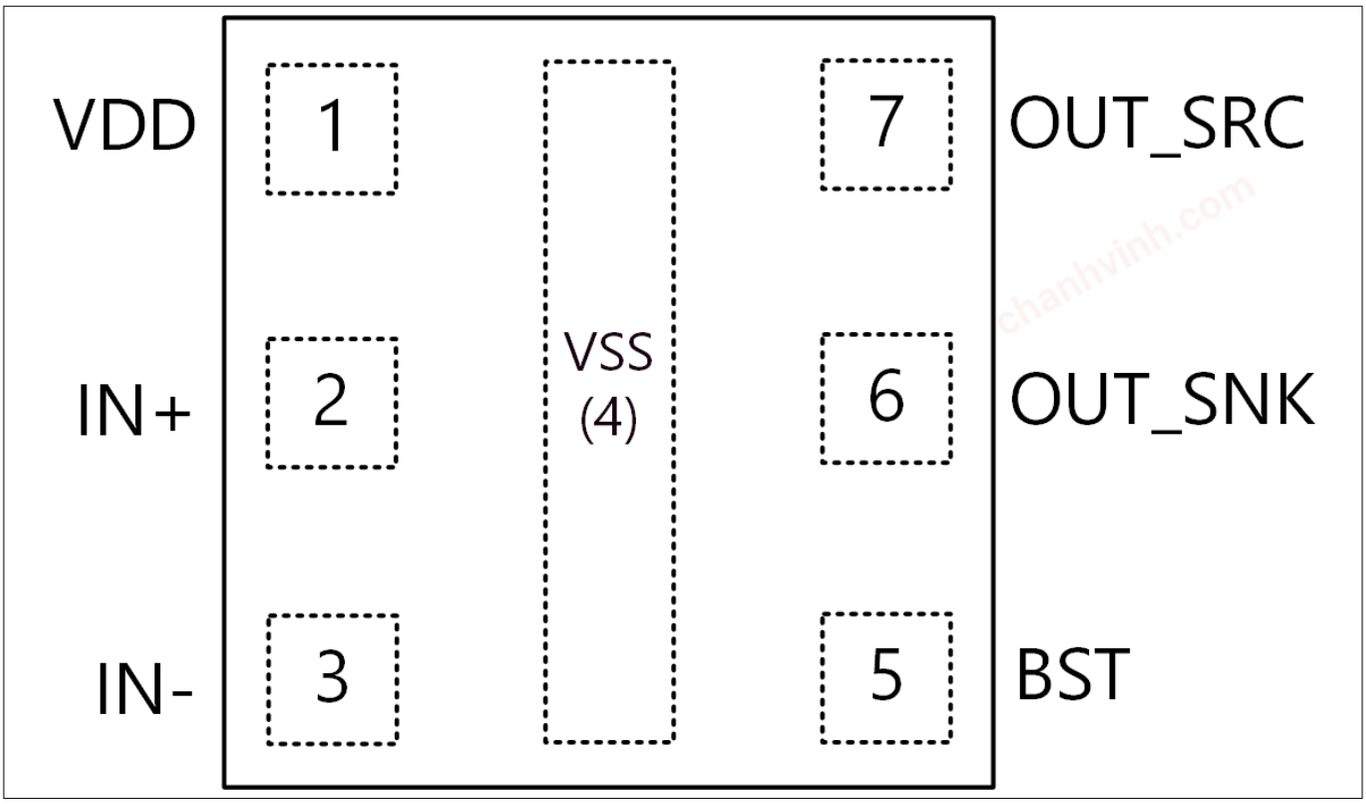


Figure 1 Pin configuration 1EDN71X6U in PG-TSNP-7 package, top view

Table 1 Pin definitions and functions

Pin	Name	Function
1	VDD	Gate drive supply.
2	IN+	Connected to PWM output of controller via 47 kΩ or 75 kΩ resistor.
3	IN-	Connected to controller ground via 47 kΩ or 75 kΩ resistor.
4	VSS	Return path for VDD and thermal dissipation pad.
5	BST	Bootstrap diode anode connection point, when used as a low-side driver in a half-bridge configuration.
6	OUT_SNK	Low-impedance gate pull-down to VSS (including active Miller clamp).
7	OUT_SRC	Low-impedance gate pull-up to VDD.

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2 Product information

2.1 Functional description

The 1EDN71x6U is a single-channel gate-driver IC optimized for compatibility with Infineon CoolGaN™ SG HEMTs, as well as other GaN HEMTs and Silicon MOSFETs. Thanks to the truly differential input feature, the gate driver output state is exclusively controlled by the voltage difference between the two inputs, independent of the driver's reference (ground) potential as long as the common-mode voltage is below 150 V (static) and 200 V (dynamic). This eliminates the risk of false triggering due to ground bounce in low-side applications, while also allowing 1EDN71x6U to address even high-side applications.

The product is equipped with several key features especially designed to enhance the performance of CoolGaN™ SG HEMTs:

- four driving strength variants to optimize switching speed without external gate resistors
- active bootstrap clamping to avoid overcharging the bootstrap capacitor during dead-time
- an active Miller clamp with exceptionally strong pull-down to avoid induced turn-on

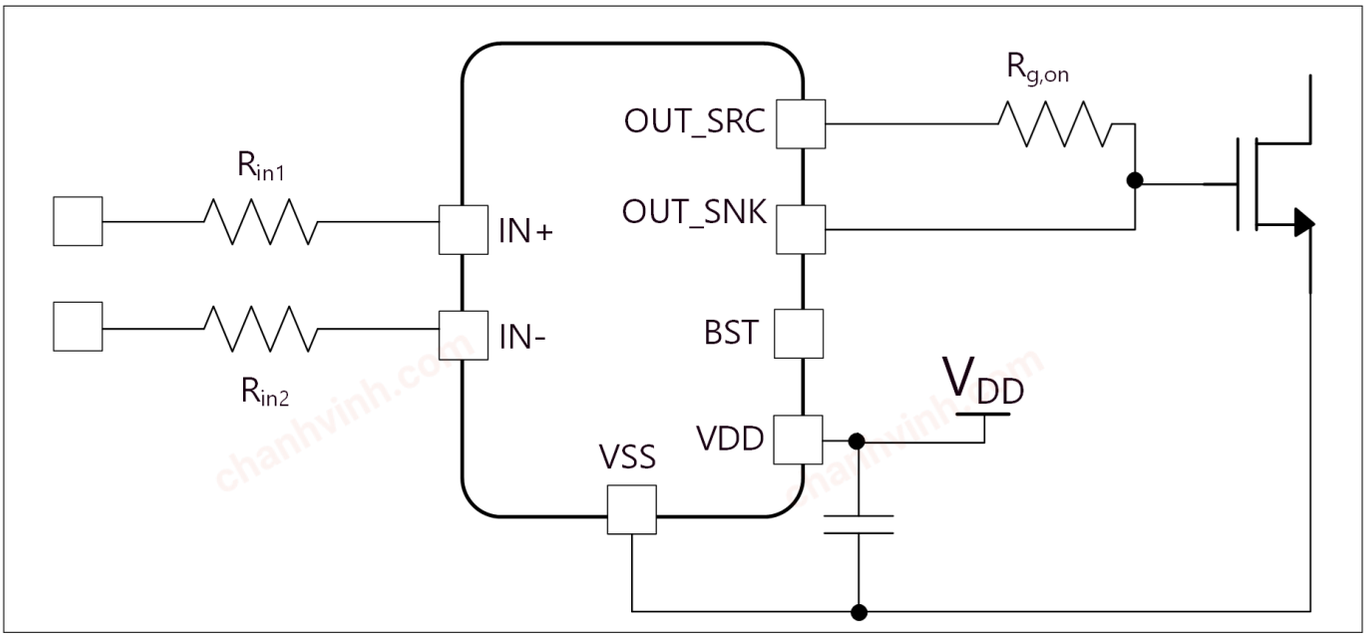


Figure 2 Typical circuit for low-side single-channel application using 1EDN71X6U to drive a CoolGaN™ SG HEMT

2.2 Truly differential input (TDI)

The TDI feature offers common-mode voltage rejection up to 150 V for static voltage and 200 V for dynamic voltage transients, enabling both low-side and high-side gate driving without the need for a digital isolator at the input. The dynamic voltage rating is relevant for any voltage spikes shorter than the specified blanking time (that is, minimum pulse width). When used as a low-side gate driver, the TDI greatly enhances ground bounce immunity during fast GaN switching transitions.

At the positive and negative signal inputs two symmetrical resistor dividers are used to scale down and compensate common mode bouncing voltages. A fully differential amplifier stage provides high common mode rejection and high sensitivity to differential input signals. The amplified differential output voltage is finally evaluated by the subsequent differential Schmitt-Trigger circuit.

At the IN+ and IN- pins, two external resistors R_{in1} and R_{in2} are used to scale down common mode voltages of up to ± 150 V to a level which can be processed by low voltage CMOS circuitry. These input resistors serve the function of "blocking" the high common-mode voltage, so that the IN+ and IN- pins of the driver are not exposed to this high voltage. As such, the selection of these resistors is critical to the proper operation of the TDI circuit.

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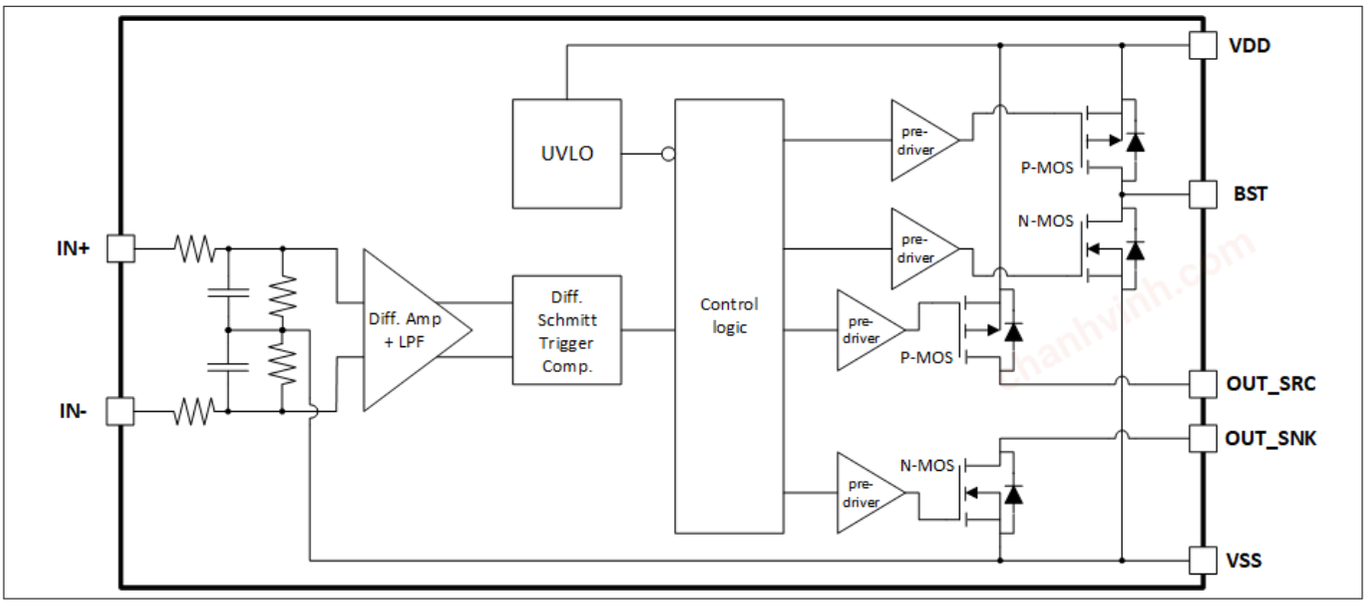


Figure 3 Functional block diagram

The resistance values for R_{in1} and R_{in2} must be selected based on the logic level of the input signals. For a 3.3 V logic, both external input resistors must be 47 kΩ. For a 5 V logic, they must be 75 kΩ. Furthermore, R_{in1} and R_{in2} must be very closely matched. A tolerance of ± 0.1 % is required to maintain control over the full common mode swing. Resistors with wider tolerance limit the common-mode range of the TDI driving circuit. Any asymmetries in these resistors may cause a a common-mode voltage to be interpreted as an input signal, including stray impedances in the PCB layout. Recommendations for a PCB layout are given later in this datasheet.

To compensate for small asymmetries in the TDI circuit, low pass filters are used to further enhance the high frequency common mode rejection. Two different input filter options are available to accommodate different designs, with a total blanking time of 20 ns for 1EDN7116U, 40 ns for 1EDN7126U, 60 ns for 1EDN7136U, and 80 ns for 1EDN7146U.

2.3 Undervoltage lockout

The undervoltage lockout (UVLO) functions ensure that the output can be switched to its high level only if the VDD supply voltage exceeds the UVLO threshold voltage.

The UVLO ensures that the transistors are not switched on if the driving voltage is too low, thereby avoiding excessive power dissipation due to linear-mode operation. The UVLO must be inactive to allow the propagation of the input control signals (IN+, IN-) to the output.

The VDD UVLO level is set to a typical value of 3.85 V, with a maximum of 4.0 V. The maximum value of the rising edge is the value that ensures all the device among the production is turned on during start up. The designer must provide a voltage higher than 4.0 V to turn on all the devices in the production of their equipment within the specified temperature range. On the opposite side, the minimum voltage necessary to switch off all the devices is the minimum of the falling edge, which is 3.6 V. Therefore, a voltage lower than 3.6 V ensures that the driver does not start switching. Once the driver has exceeded the UVLO, the supply voltage must remain above the maximum falling edge level of 3.9 V to avoid a UVLO shutdown. The hysteresis is the voltage gap between rising edge and falling edge, which ensures some margin on noise effects such as false turn off.

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The output states depend on the inputs configuration and the status of the VDD UVLO. The truth table of the driver is represented below.

Table 2 Input logic truth table

Differential input	UVLO VDD	OUT_SNK	OUT_SRC	BST
X	ACTIVE	HiZ	HiZ	HiZ
L	INACTIVE	L	HiZ	L
H	INACTIVE	HiZ	H	H

Where:

- UVLO active means V_{DD} < UVLOVDDL
- UVLO inactive means V_{DD} > UVLOVDDH
- Differential input = L means (V_{IN+} - V_{IN-}) < input logic threshold
- Differential input = H means (V_{IN+} - V_{IN-}) > input logic threshold

2.4 Minimum input pulse

The minimum input pulse is the shortest duration pulse at the differential input that will generate an output pulse. Pulses with durations shorter than the minimum pulse are neglected and therefore will not generate any output pulse. Once the input pulse has sufficient duration to be propagated, the duration of the output pulse is equal to the duration of the input pulse, having therefore a linear transfer function between input and output.

The minimum input pulse is specified here as "shortest input pulse transferred to the output." The maximum value for this parameter is the pulse width at which all the drivers in production will provide an output signal. In other words, the designer must provide a pulse width longer than the maximum specified value to ensure an output pulse for every driver of their equipment. Likewise, any pulses shorter than the minimum specified value will be ignored by all drivers in production. This minimum specification can be treated as the guaranteed blanking time for de-glitching, which helps to prevent spurious switching during common-mode transient events.

2.5 Driver outputs

The output stage of the driver has a peak source and sink current as defined for the given product variant, which corresponds to an equivalent resistance of the pull-up and pull-down transistor. The designer can optimize the switching speed of the driven transistor by selecting one of the four product variants, without the need for external gate resistors. If external gate resistors are used, it is highly recommended to avoid placing a resistor in the output sinking path, as this limits the effectiveness of the active Miller clamp described in the next section.

Source and sink outputs are actively held low with a clamp in case of floating inputs or during startup or power down. Under any situation, outputs are held under defined conditions to avoid unstable or unknown behavior of the driven transistor.

2.6 Active Miller clamp

The sink output of the gate driver has an active Miller clamp feature to provide high immunity to spurious turn-on events. During a turn-off transition, the peak sinking current and equivalent pull-down resistance is defined according to the product variant. However, once the driver detects that the gate voltage (at the sink output) has fallen below 0.4 V, the active Miller clamp is engaged within 3 ns, increasing the strength of the Sink output significantly. With the clamp engaged, all four product variants can sink up to 5 A, with an equivalent pull-down resistance of 0.3 Ω. This feature allows the designer to optimize the turn-off speed without sacrificing the driver's "keep-off" strength. If an external gate resistor is placed at the sink output, the effectiveness of the active Miller clamp is reduced.

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2.7 Active bootstrap clamp

When using the bootstrapping technique to supply the high-side gate driver in a half-bridge topology, it is sometimes necessary to regulate the bootstrap capacitor voltage to avoid damaging the gate of the high-side transistor. This is especially important for GaN transistors for two reasons:

1. GaN SG HEMTs are often sensitive to gate over-voltage, with driving voltages typically in the range of 5 V +/- 1 V.
2. The "body diode" mechanism of GaN transistors causes a higher voltage drop than MOSFETs, which leads to excessive over-charging of the bootstrap capacitor during dead-time conduction.

In a half-bridge configuration, the bootstrap capacitor is normally charged during the low-side switch conduction time. Figure 4 shows this charging path, which includes the power supply (VDD), the bootstrap diode, current-limiting resistor, the bootstrap capacitor, and the low-side switch. When the low-side switching is turned fully on, the voltage applied to the bootstrap capacitor is slightly lower than VDD, due to the drop across the bootstrap diode, which can be partially compensated by the drop across the low-side transistor. However, during dead-time intervals, the low-side transistor operates in "body diode" mode, with a voltage drop in the range of 1.5 ~ 2.5 V, or even higher when a negative off-state V_{GS} is applied. This causes over-charging of the bootstrap capacitor during the dead-time, resulting in a bootstrap voltage that varies significantly with dead-time duration and operating current, with a high risk of exceeding the maximum rated V_{GS} of the driven transistor.

This is not a problem for a typical MOSFET, since the operating range of the gate is fairly wide. However, this variable bootstrap capacitor voltage may pose a serious risk of damage to GaN Schottky gates. Therefore, it is necessary to apply some form of regulation to this circuit. For example, a Zener diode can be used as shown in Figure 4 , as long as the dead-time interval is well-controlled and paired with a current-limiting resistor that avoids overheating the Zener diode.

The 1EDN71X6U driver offers an alternative bootstrap clamping scheme. Figure 5 shows the implementation of this bootstrap clamping scheme in a half-bridge circuit. The clamp circuit avoids over-charging the bootstrap capacitor instead of directly regulating the capacitor voltage, which would likely contribute additional losses. Rather than connecting the bootstrap diode to the VDD supply rail, it is connected to the BST output of the low-side driver. The BST output operates as a clone of the source and sink output pins, synchronized to the timing of the low-side transistor turning on and off. Therefore, the bootstrap diode can only conduct current when the low-side transistor is turned fully on, but not when it is operating in "body diode" mode during dead-time.

The active bootstrap clamping scheme is very useful in regulating the high-side driving voltage without the need for additional components. However, in applications where over-charging of the bootstrap capacitor is desired, the bootstrap diode can be connected to the VDD pin instead of the BST pin. A Zener-based regulation scheme is recommended in this case, as shown in Figure 4.

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2 Product information

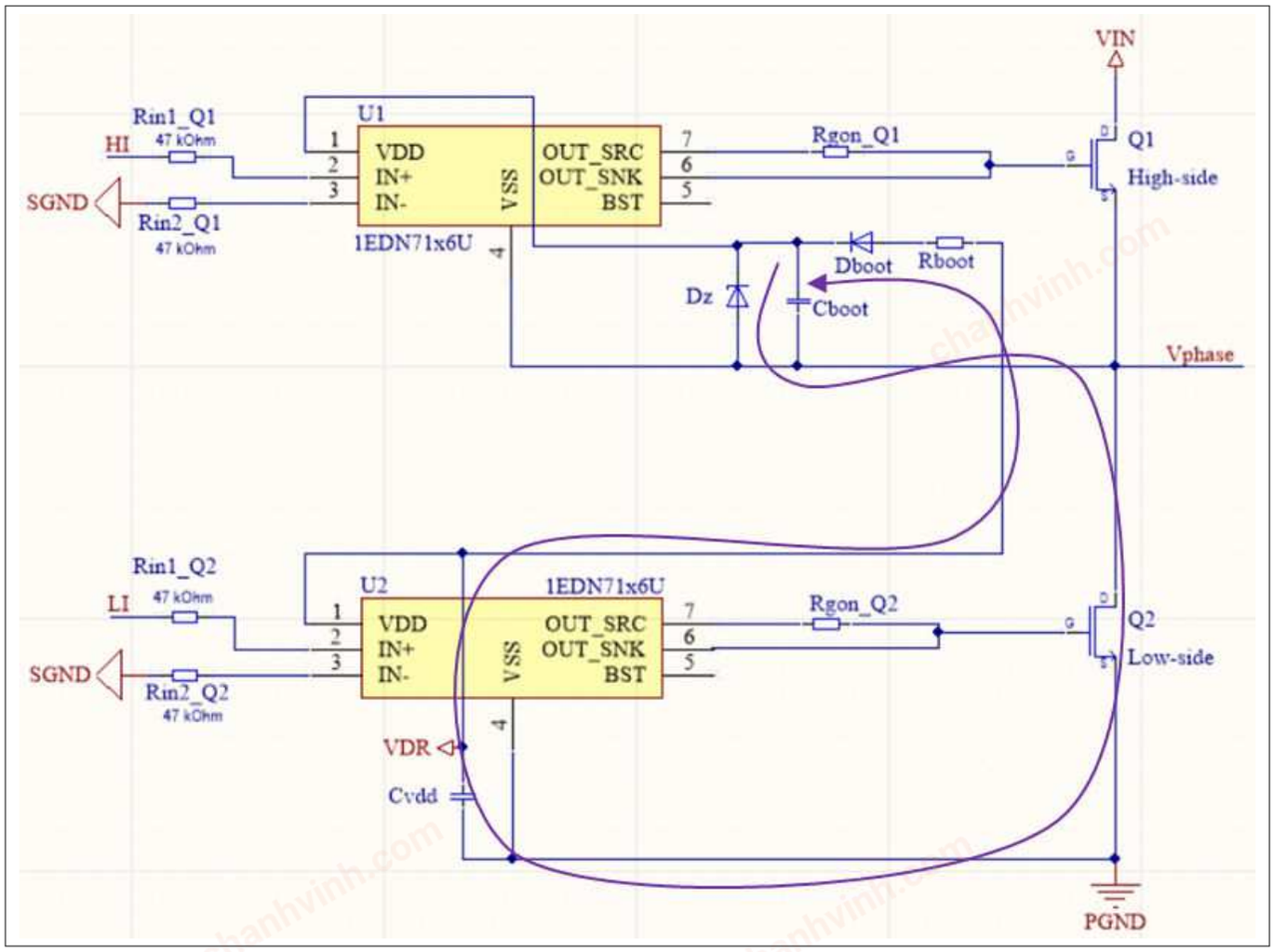


Figure 4 Half-bridge with Zener bootstrap regulation

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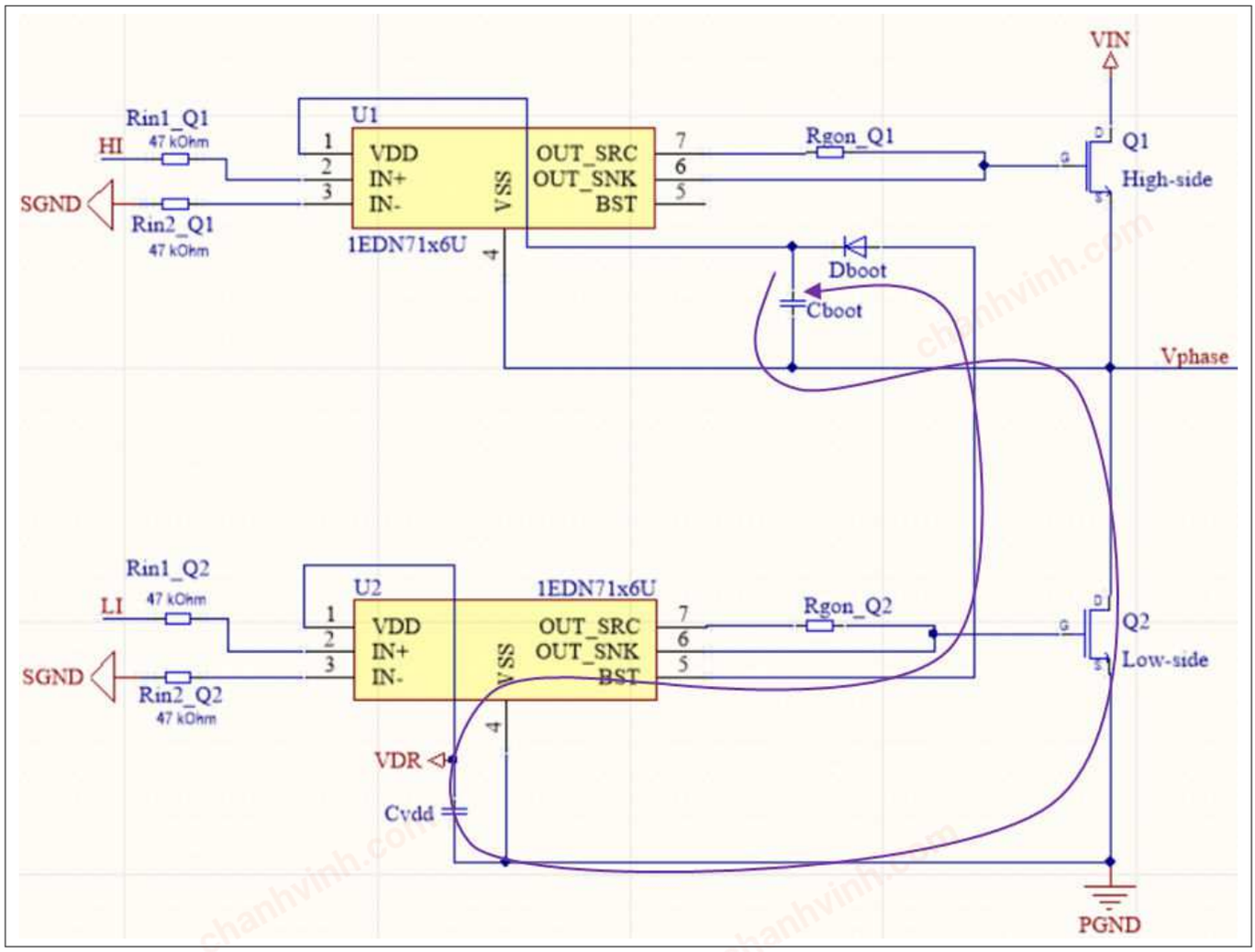


Figure 5 **Half-bridge with active bootstrap clamping**

2.8 Unpowered gate clamp

The unpowered gate clamp circuit ensures that the driver output is pulled low when no supply voltage is applied to the driver. It is common practice to place a resistor between the gate and source of transistors to ensure that there is no spurious voltage when the system is powered off. However, this is not necessary with the 1EDN71x6U. The driver has an internal pull-down MOSFET between the OUT_SNK pin and VSS pin, which pulls down the gate voltage to VSS with a peak current capability of 3 mA, whenever VDD is not sufficiently supplied to turn on the driver. Once the 1EDN71x6U is fully powered on, this pull-down MOSFET is disabled.

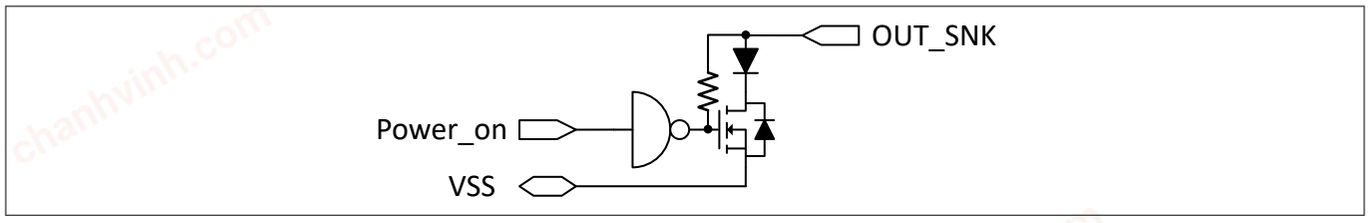


Figure 6 **Functional diagram of unpowered gate clamp circuit**

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3 General product characteristics

3.1 Absolute maximum ratings

All voltages are referred to VSS unless otherwise specified.

Table 3 Absolute maximum ratings

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Driver supply	V_{DD}	-0.3	–	12	V	
Driver supply, transient	V_{DD}	–	–	13.2	V	< 3 ns
Voltage at IN+ pin	V_{IN+}	-8.5	–	8.5	V	
Voltage at IN- pin	V_{IN-}	-8.5	–	8.5	V	
Voltage at OUT_SRC, OUT_SNK, BST pins	V_{OUT_SRC}, V_{OUT_SNK}, V_{BST}	-0.3	-	VDD + 0.3	V	
Junction temperature	T_J	-40	–	150	°C	
Storage temperature	T_S	-55	–	150	°C	
Soldering temperature		–	–	260	°C	

3.2 Recommended operating conditions

The following operating conditions must not be exceeded to ensure correct operation and reliability of the device. All parameters specified in the following tables refer to these operating conditions, unless noted otherwise.

Table 4 Recommended operating conditions

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Supply voltage	V_{DD}	4.2	–	11	V	
Operating frequency	F_{SW}	–	–	15	MHz	[1]
Common mode voltage range (static)	*CMR*	-150	–	150	V	R_{ext} = 47k ± 0.1%, V_{logic} = 3.3 V.

(table continues...)

[1] Verified by design/characterization. Not subject to production test.

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Table 4 (continued) Recommended operating conditions

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Common mode voltage range (dynamic)	CMR_{dyn}	-200	–	200	V	R_{ext} = 47k ± 0.1%, V_{logic} = 3.3 V. Duration of voltage transient event must be shorter than specified blanking time. [1)]
Common mode voltage slew rate	$CMSR$	–	–	100	V/ns	[1)]

3.3 ESD ratings

Table 5 ESD ratings

Symbol	Description	Value	Unit
ESD_{HBM}	Human Body Model sensitivity as per ANSI/ESDA/JEDEC JS-001	1500	V
ESD_{CDM}	Charged Device Model sensitivity as per ANSI/ESDA/JEDEC JS-002	1000	V

3.4 Thermal resistance

Table 6 Thermal resistance

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Junction-to-ambient thermal resistance	R_{thJA}	–	80	–	°C/W	JEDEC 2s2p with thermal vias. [2)]
Junction-to-case thermal resistance - bottom	$R_{thJC(BOT)}$	–	28	–	°C/W	
Junction-to-case thermal resistance - top	$R_{thJC(TOP)}$	–	114	–	°C/W	

1 Verified by design/characterization. Not subject to production test.
2 Obtained in a simulation on a JEDEC-standard 2s2p four-layer PCB with thermal vias, as specified in JESD51-7, in an environment described in JESD51-2a.

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3.5 Static electrical characteristics

V_{DD} - V_{SS} = 5 V, T_c = - 40°C to 125°C unless otherwise specified.

Table 7 Static electrical characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Undervoltage lockout thresholds						
VDD supply UVLO rising threshold	$UVLO_{VDDH}$	3.7	3.85	4	V	
VDD supply UVLO falling threshold	$UVLO_{VDDL}$	3.6	3.75	3.9	V	
Current consumption						
VDD quiescent current	I_{QDD}	–	–	1.8	mA	IN+ = IN- = 0 V.
VDD current consumption when switching	I_{ODD}	–	–	2.6	mA	f_{SW} = 500 kHz, no load on OUT_SRC/ OUT_SNK and no load on BST. Apply PWM to IN+, set IN- = 0 V. Common mode = 0 V.
Input characteristics						
Differential input voltage threshold for low-high transition	ΔV_{RinH}	1.7	1.95	2.2	V	Thresholds valid for R_{EXT} = 47 kΩ. VCM = 0 V and T = 25 °C.
Differential input voltage threshold for low-high transition	ΔV_{RinH}	1.2	1.95	2.65	V	Thresholds valid for R_{EXT} = 47 kΩ. VCM = -150 V to 150 V.
Differential input voltage threshold for high-low transition	ΔV_{RinL}	1.1	1.35	1.6	V	Thresholds valid for R_{EXT} = 47 kΩ. VCM = 0 V and T = 25 °C.
Differential input voltage threshold for high-low transition	ΔV_{RinL}	0.7	1.35	2.15	V	Thresholds valid for R_{EXT} = 47 kΩ. VCM = -150 V to 150 V.

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3.6 Driver output characteristics

Table 8 Driver output characteristics

Parameter	Symbol	Typical values				Unit	Note or condition
		1EDN7116U	1EDN7126U	1EDN7136U	1EDN7146U		
Peak source current	I_{OUT_SRC}	2	1.5	1	0.5	A	VDD = 5 V, OUT_SRC = 0 V [1]
Peak sink current	I_{OUT_SNK}	2	1.5	1	0.5	A	VDD = 5 V, OUT_SNK = 5 V [1]
Peak sink current w/ Miller clamp	$I_{OUT_SNK_MC}$	5	5	5	5	A	VDD = 5 V, OUT_SNK = 5 V [1]
Pull-up resistance	R_{PU}	0.8	1.1	1.6	3.3	Ω	I_SRC = 100 mA
Pull-down resistance	R_{PD}	0.7	1.0	1.5	3.0	Ω	I_SNK = 100 mA
Pull-down resistance w/ Miller clamp	R_{PD_MC}	0.3	0.3	0.3	0.3	Ω	I_SNK = 100 mA
Active Miller clamp voltage threshold	V_{MC_TH}	0.4	0.4	0.4	0.4	V	[1]
Active Miller clamp propagation delay	T_{MCD}	3	3	3	3	ns	No load. [1]
Unpowered gate clamp sinking current	$I_{OUT_SNK_UGC}$	3	3	3	3	mA	VDD floating. 1.2 V applied externally to OUT_SNK.
Rise time	T_R	3	4	5.5	11	ns	OUT_SRC and OUT_SNK shorted. C_L = 1 nF, VDD = 5 V [1]
Fall time	T_F	3	4	5.5	11	ns	
BST peak source current	I_{BST_SRC}	2	2	2	2	A	VDD = 5 V, BST = 0 V [1]
BST peak sink current	I_{BST_SNK}	2	2	2	2	A	VDD = 5 V, BST = 5 V [1]
BST pull-up resistance	R_{BST_PU}	0.8	0.8	0.8	0.8	Ω	I_BST_SRC = 100 mA
BST pull-down resistance	R_{BST_PD}	0.7	0.7	0.7	0.7	Ω	I_BST_SNK = 100 mA

1) Verified by design/characterization. Not subject to production test.

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3.7 Timing characteristics

Timings are obtained considering OUT_SRC and OUT_SNK shorted together, C_{LOAD} = 0 nF and over common mode range -150 V to 150 V, VDD = 5 V, R_{EXT} = 47 kΩ unless specified otherwise.

Table 9 Timing characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Startup time, after UVLO threshold is reached	t_{ST}	_	12	20	µs	VSS = 0 V, T_j = 25°C.
Turn-on propagation delay matching OUT to BST	ΔT_{LH_BST}	-2	–	2	ns	Calculated as TLH - $TLH_{BST.}$ VCM = 0 V, T_j = 25°C.
Turn-off propagation delay matching OUT to BST	ΔT_{HL_BST}	-2	–	2	ns	Calculated as THL - $THL_{BST.}$ VCM = 0 V, T_j = 25°C.
1EDN7116U						
Turn-on propagation delay	*TLH*	53	55	57	ns	VCM = 0 V, T_j = 25°C.
Turn-off propagation delay	*THL*	53	55	57	ns	VCM = 0 V, T_j = 25°C.
Propagation delay matching	*ΔTLH_HL*	-2.2	0	2.2	ns	Calculated as TLH - THL. VCM = 0 V, T_j = 25°C.
Shortest input pulse transferred to the output	*TPW_MIN*	20	–	25	ns	VCM = 0 V, T_j = 25°C.
1EDN7126U						
Turn-on propagation delay	*TLH*	73	75	77	ns	VCM = 0 V, T_j = 25°C.
Turn-off propagation delay	*THL*	73	75	77	ns	VCM = 0 V, T_j = 25°C.

(table continues...)

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Table 9 (continued) Timing characteristics

Parameter	Symbol	Values			Unit	Note or condition
		Min.	Typ.	Max.		
Propagation delay matching	*ΔTLH_HL*	-2.8	–	2.8	ns	Calculated as TLH - THL. VCM = 0 V, T_j = 25°C.
Shortest input pulse transferred to the output	*TPW_MIN*	40	–	47	ns	VCM = 0 V, T_j = 25°C.
1EDN7136U						
Turn-on propagation delay	*TLH*	101	105	109	ns	VCM = 0 V, T_j = 25°C.
Turn-off propagation delay	*THL*	101	105	109	ns	VCM = 0 V, T_j = 25°C.
Propagation delay matching	*ΔTLH_HL*	-3.4	–	3.4	ns	Calculated as TLH - THL. VCM = 0 V, T_j = 25°C.
Shortest input pulse transferred to the output	*TPW_MIN*	60	–	71	ns	VCM = 0 V, T_j = 25°C.
1EDN7146U						
Turn-on propagation delay	*TLH*	121	125	129	ns	VCM = 0 V, T_j = 25°C.
Turn-off propagation delay	*THL*	121	125	129	ns	VCM = 0 V, T_j = 25°C.
Propagation delay matching	*ΔTLH_HL*	-3.8	–	3.8	ns	Calculated as TLH - THL. VCM = 0 V, T_j = 25°C.
Shortest input pulse transferred to the output	*TPW_MIN*	80	–	93	ns	VCM = 0 V, T_j = 25°C.

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4 Typical characteristics

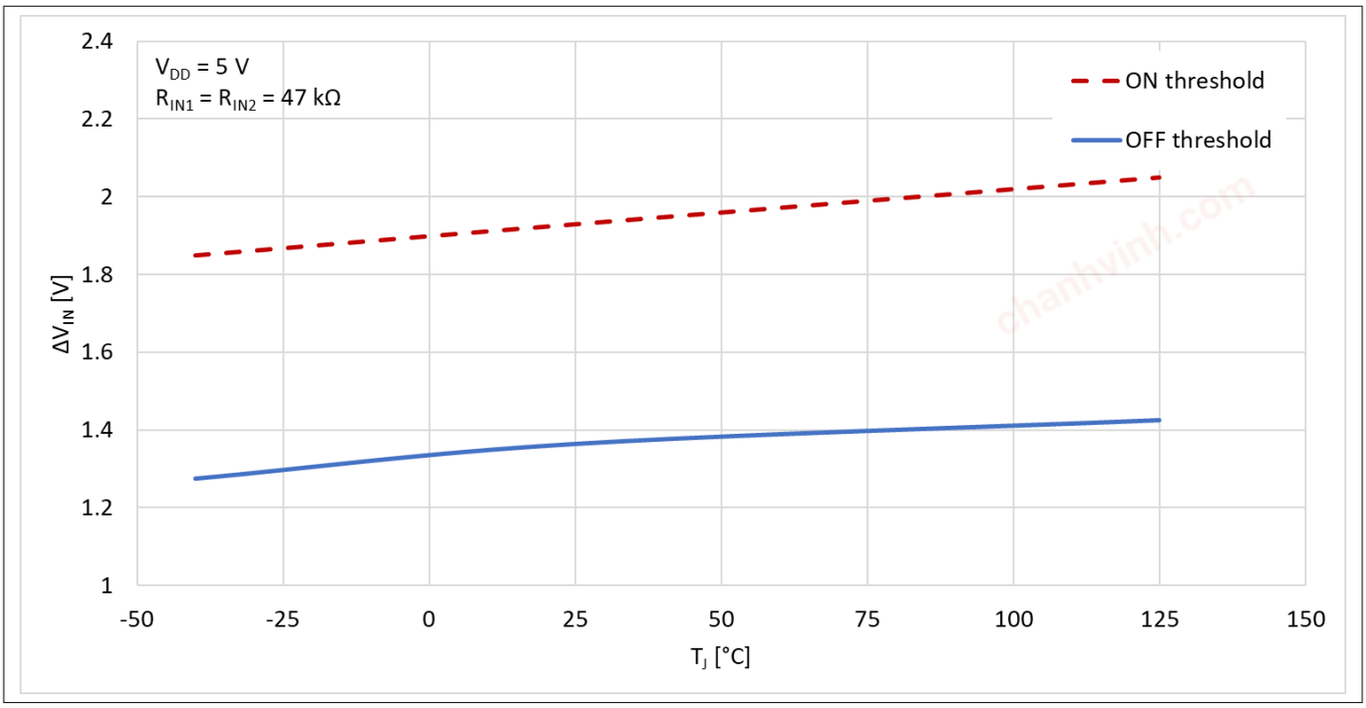


Figure 7 Differential input voltage threshold versus temperature

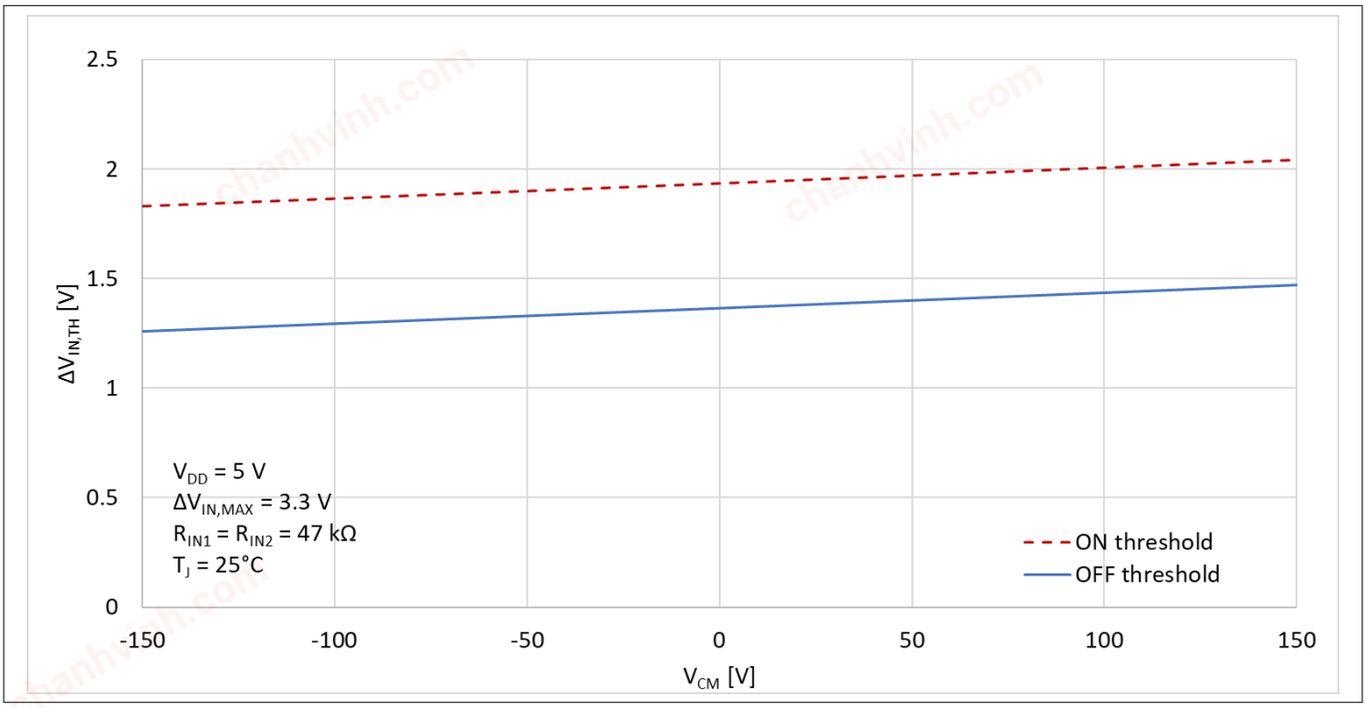


Figure 8 Differential input voltage threshold versus common mode voltage

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4 Typical characteristics

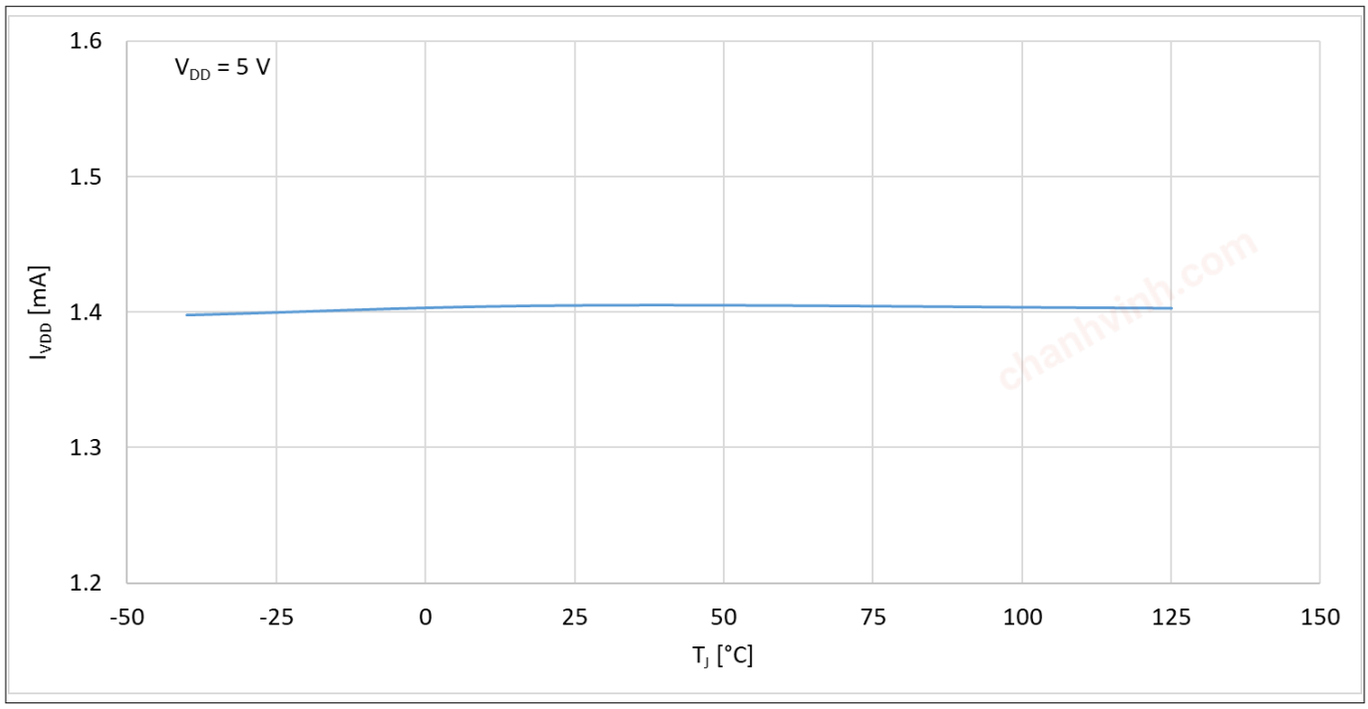


Figure 9 **Quiescent current versus temperature**

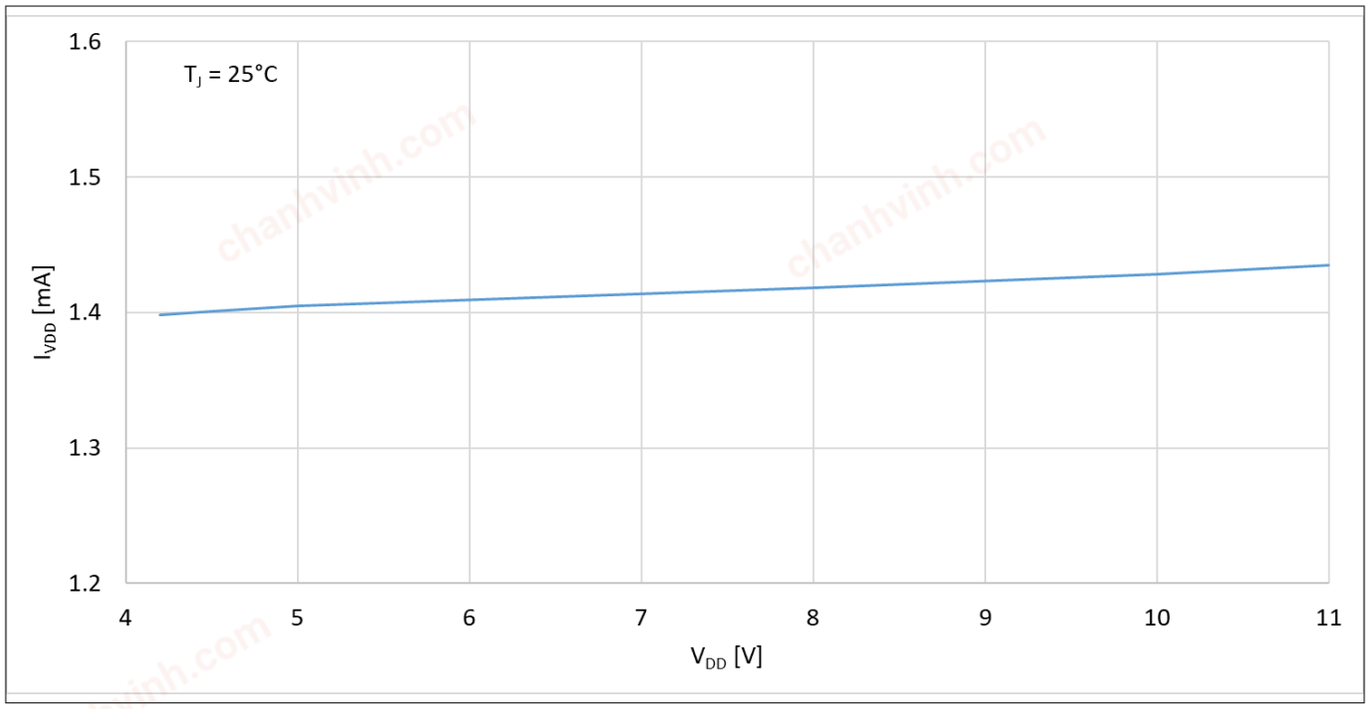


Figure 10 **Quiescent current versus supply voltage**

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4 Typical characteristics

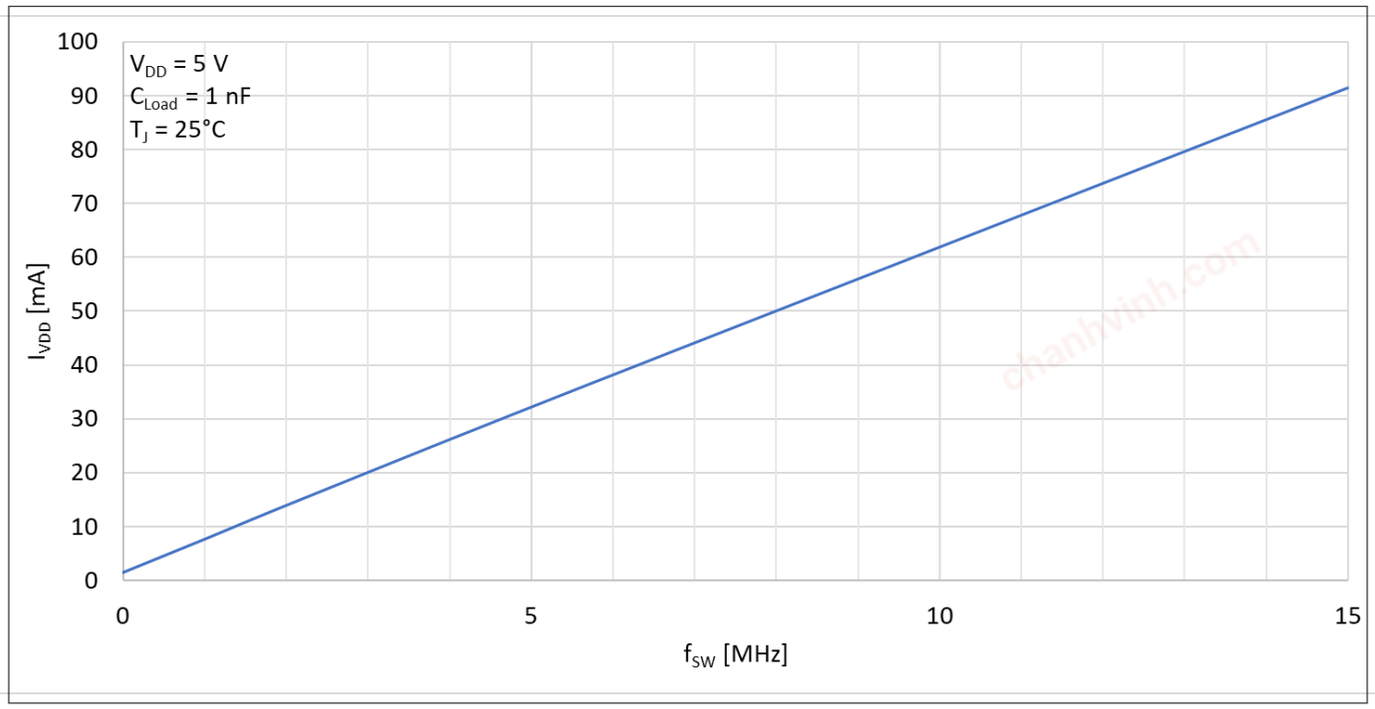


Figure 11 **Operating current with load versus frequency**

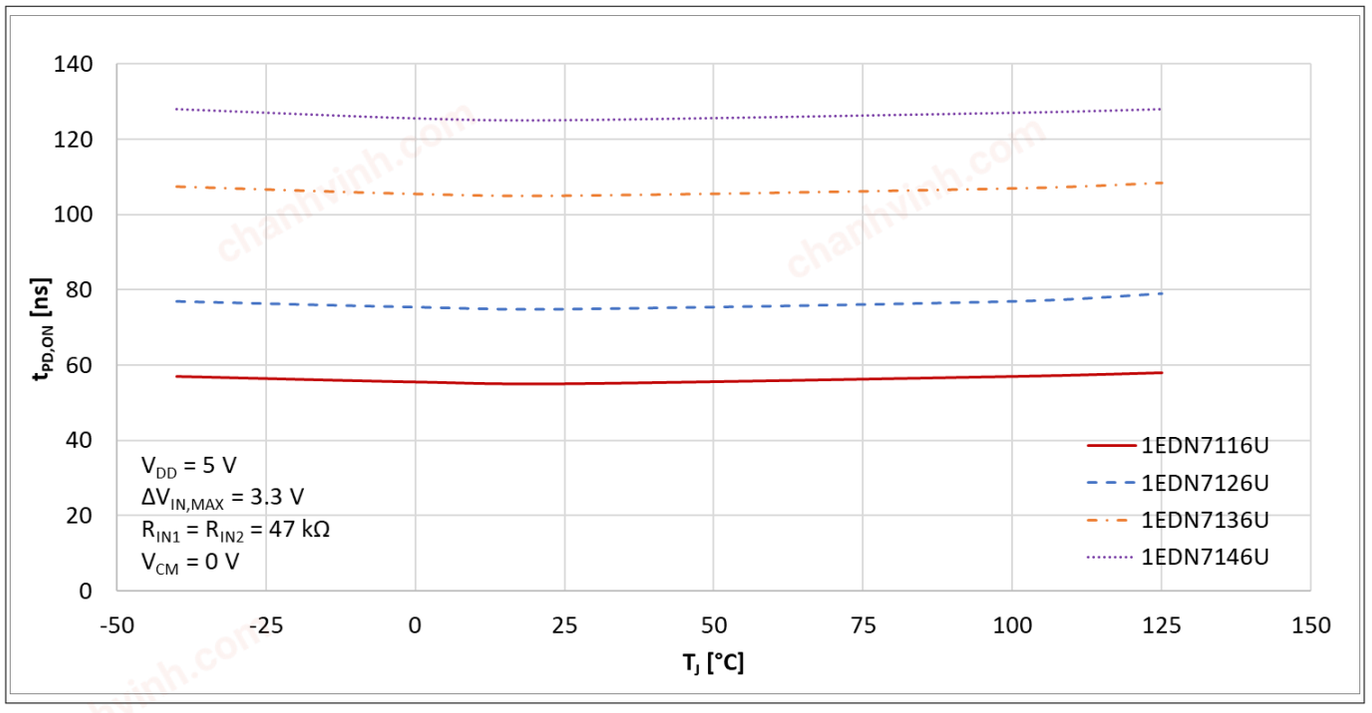


Figure 12 **Turn-on propagation delay versus temperature**

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4 Typical characteristics

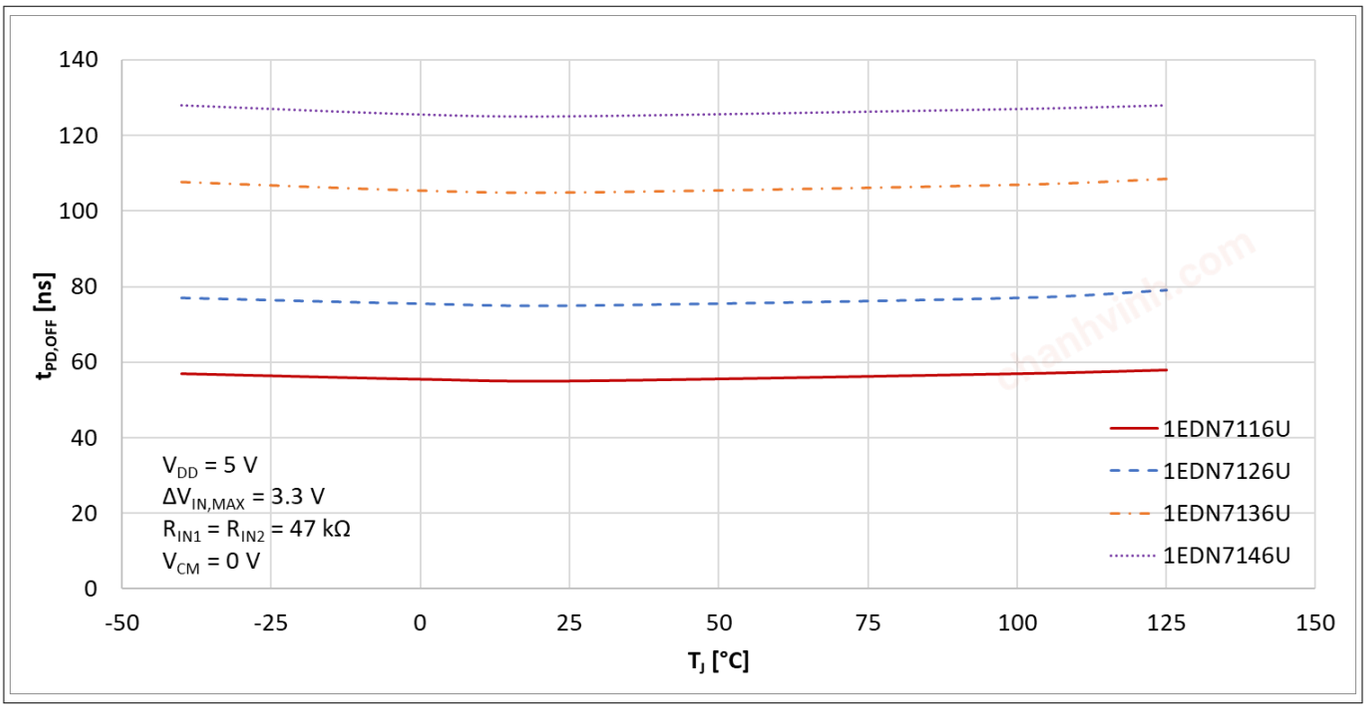


Figure 13 Turn-off propagation delay versus temperature

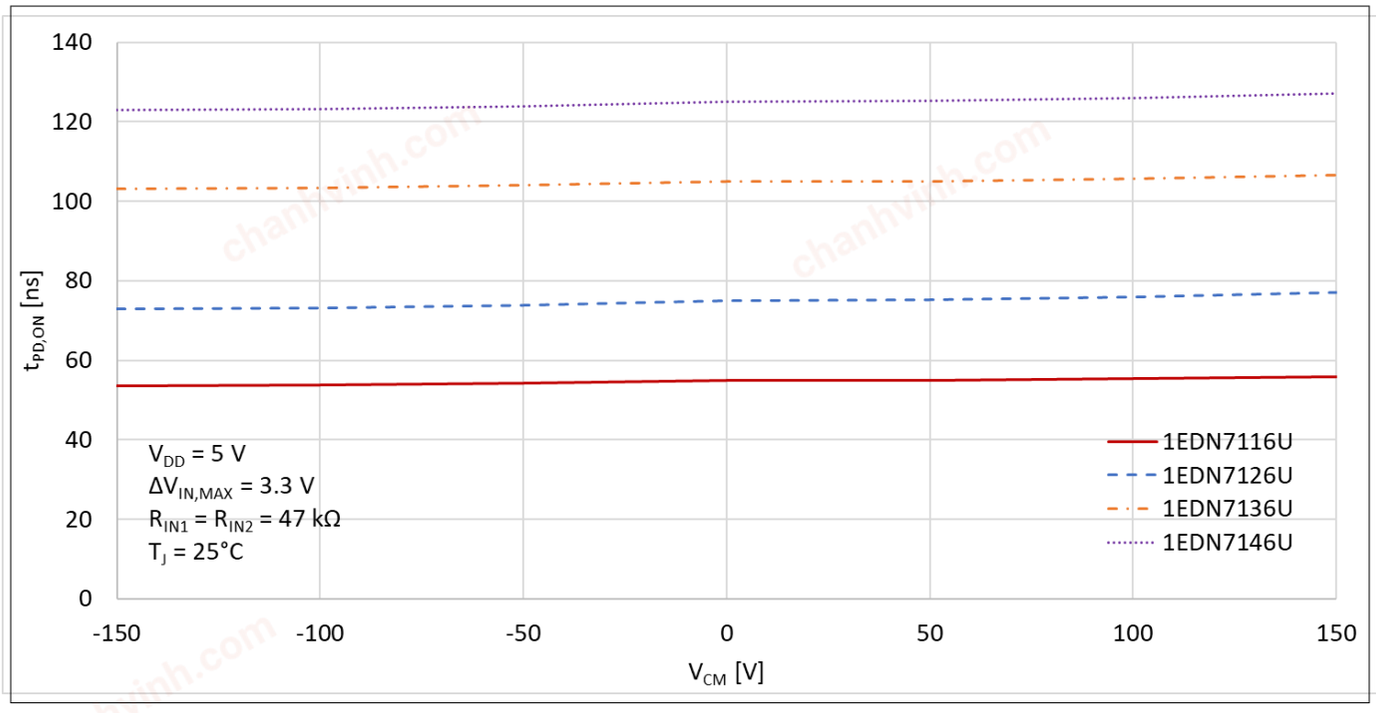


Figure 14 Turn-on propagation delay versus common mode voltage

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4 Typical characteristics

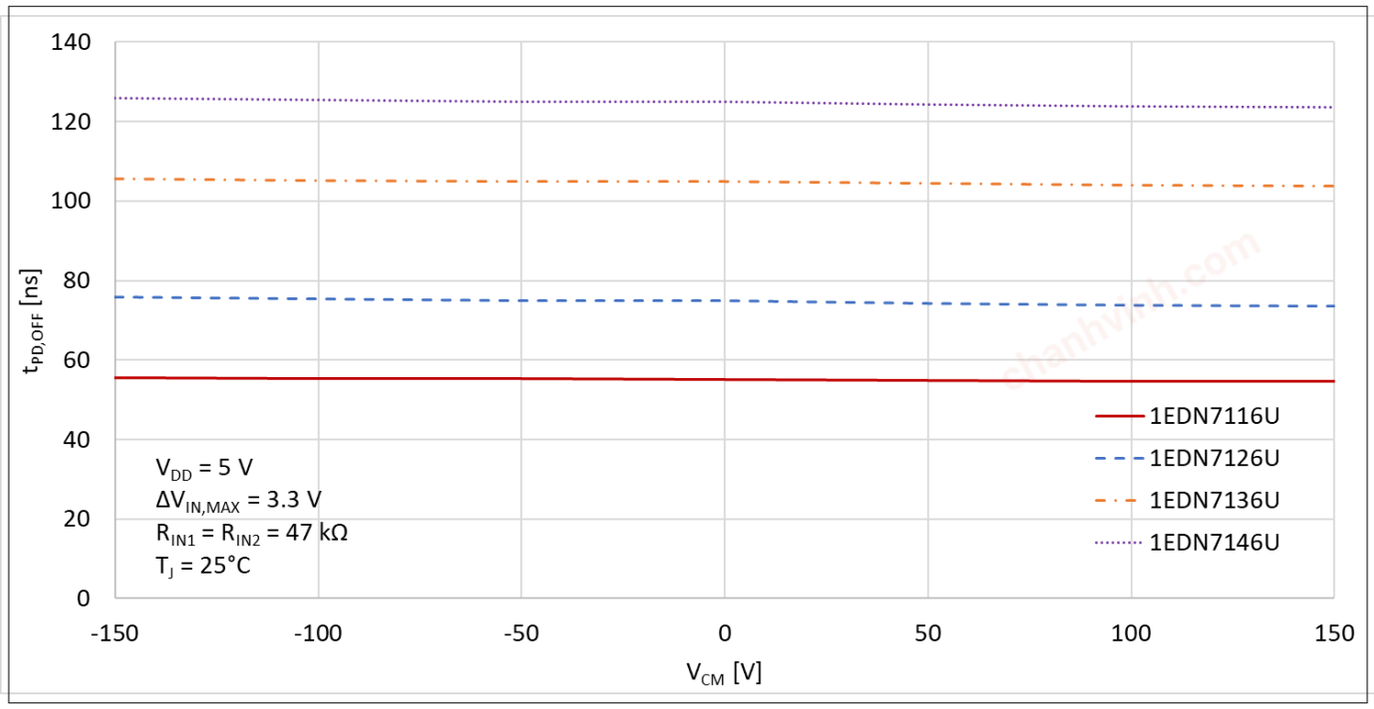


Figure 15 Turn-off propagation delay versus common mode voltage

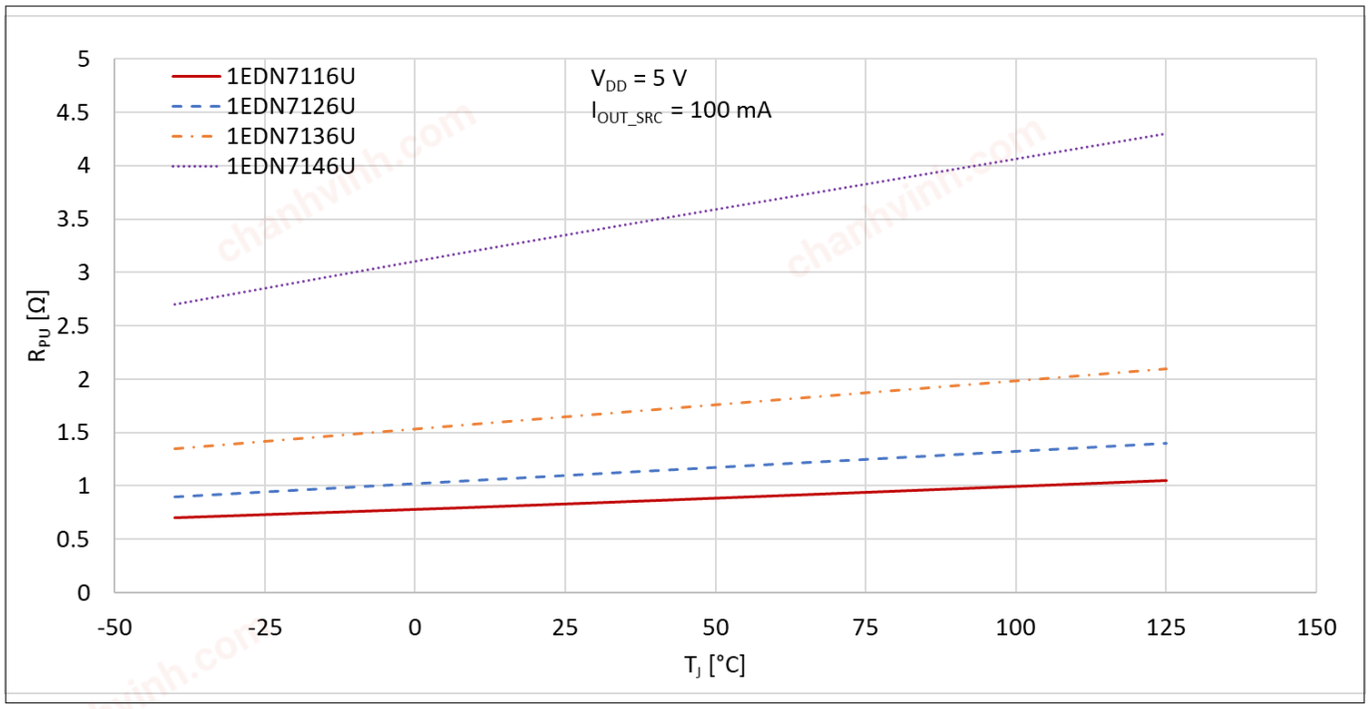


Figure 16 OUT_SRC pull-up resistance versus temperature

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4 Typical characteristics

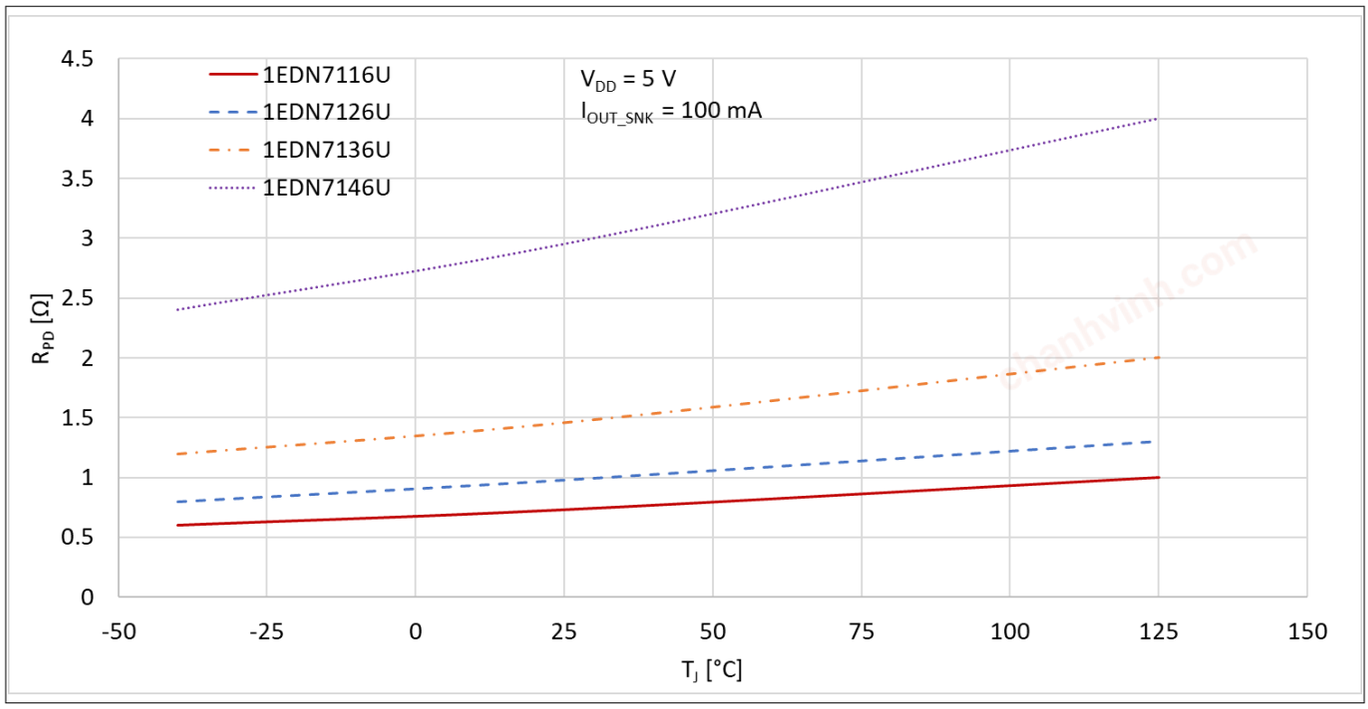


Figure 17 **OUT_SNK pull-down resistance versus temperature (before active Miller clamp is engaged)**

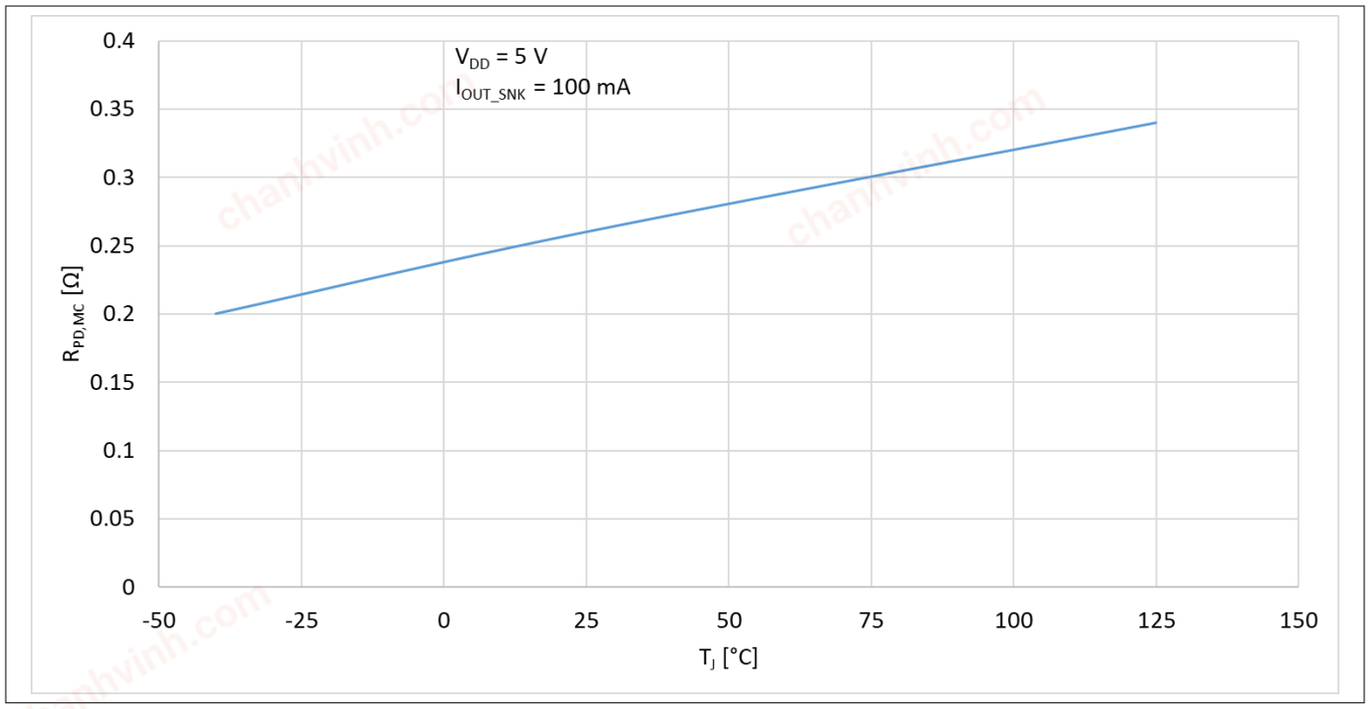


Figure 18 **OUT_SNK pull-down resistance versus temperature (after Miller clamp is engaged)**

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4 Typical characteristics

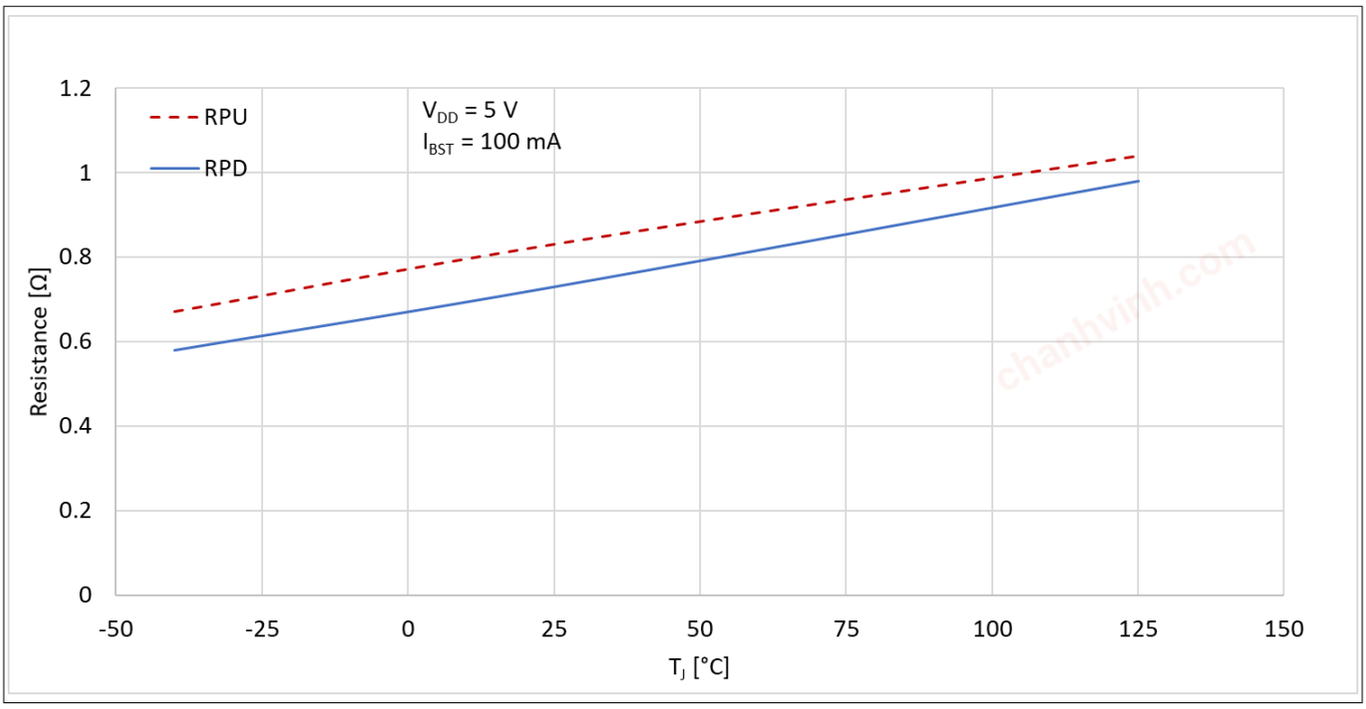


Figure 19 BST pull-up and pull-down resistance versus temperature

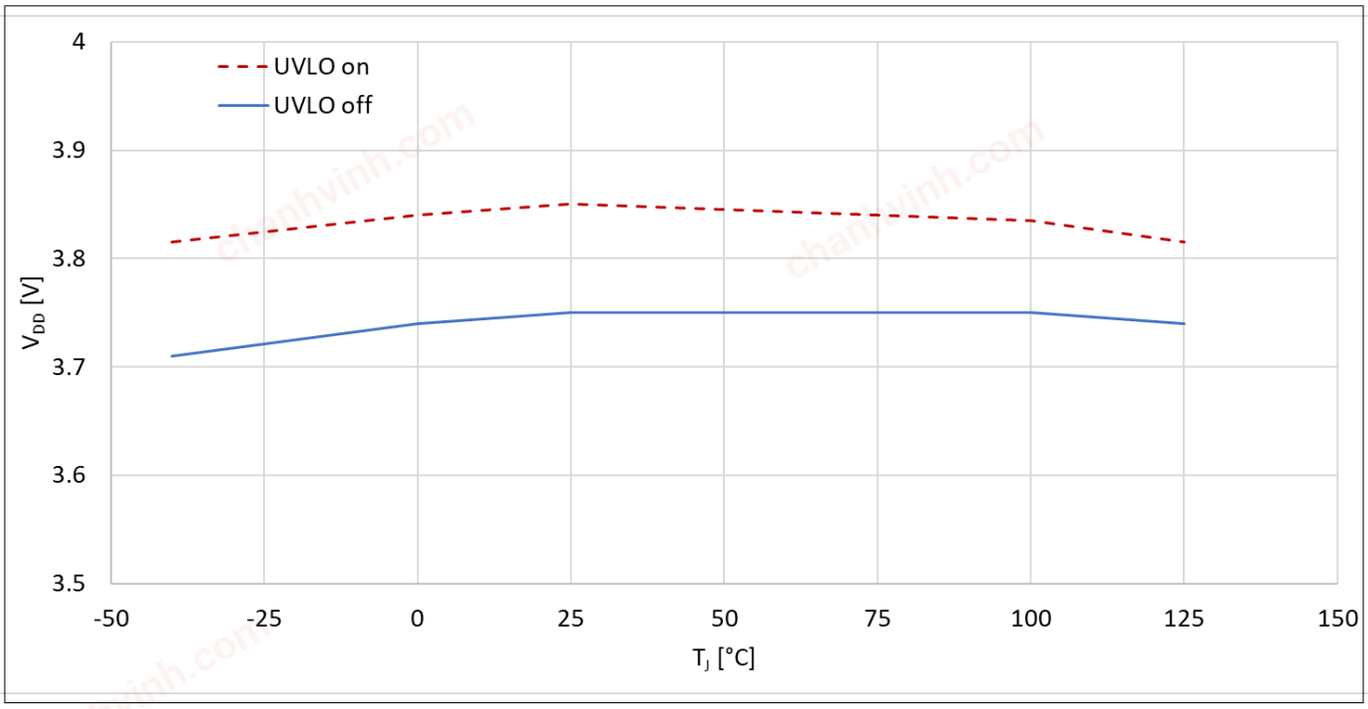


Figure 20 Undervoltage lockout threshold versus temperature

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4 Typical characteristics

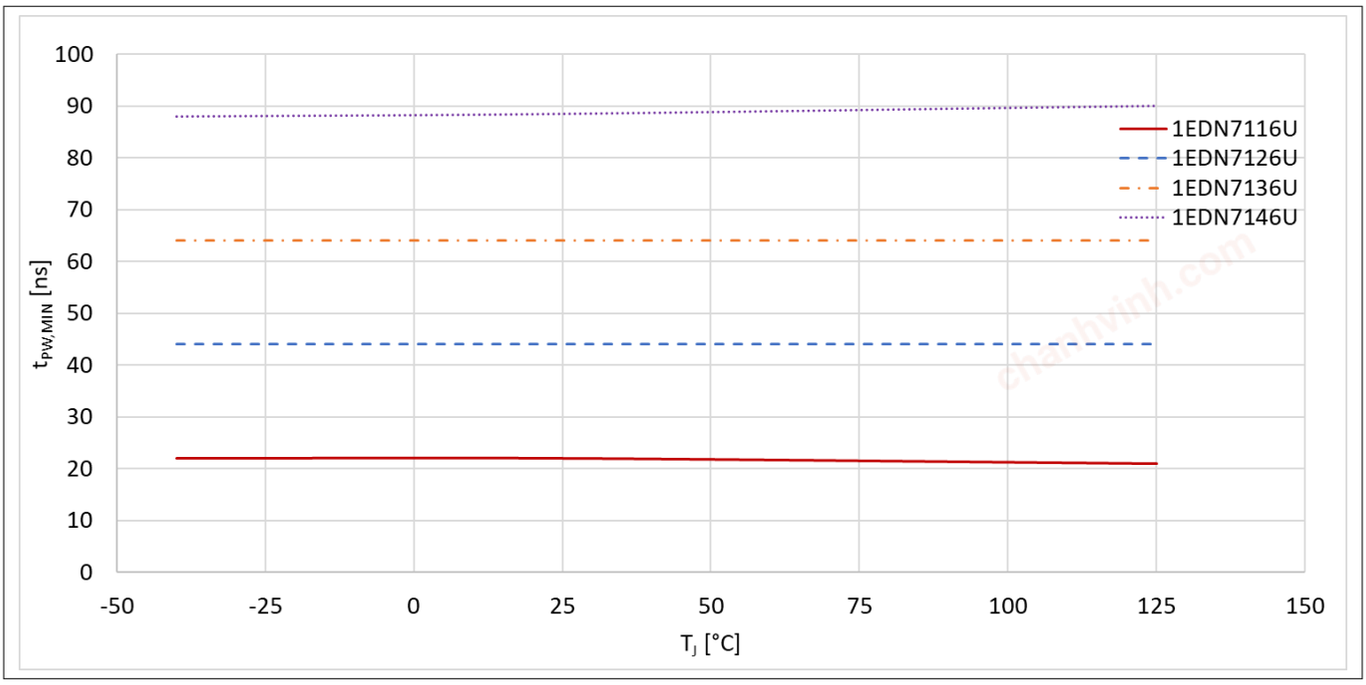


Figure 21 Shortest input pulse transferred to output versus temperature

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5 Application information

5.1 Typical application circuits

The 1EDN71x6U can be used as a single low-side driver or a single high-side driver, and two can be used together to drive a half-bridge. Figure 22 depicts an example circuit schematic for a single-device driver. Figure 4 and Figure 5 show two examples of half-bridge circuit schematics with two 1EDN71x6U, with conventional bootstrapping and Zener regulation in the first, and active bootstrap clamping enabled in the second. Figure 23 shows an additional example of half-bridge implementation, in this case with cross-connected PWM inputs for the high-side and low-side drivers. This option adds robustness against accidental cross-conduction in case the controller ever generates overlapping PWM signal. However, it may also limit the minimum dead-time as measured at the gate signals of the driven devices, due to asymmetrical turn-on and turn-off delay times of the driven transistors.

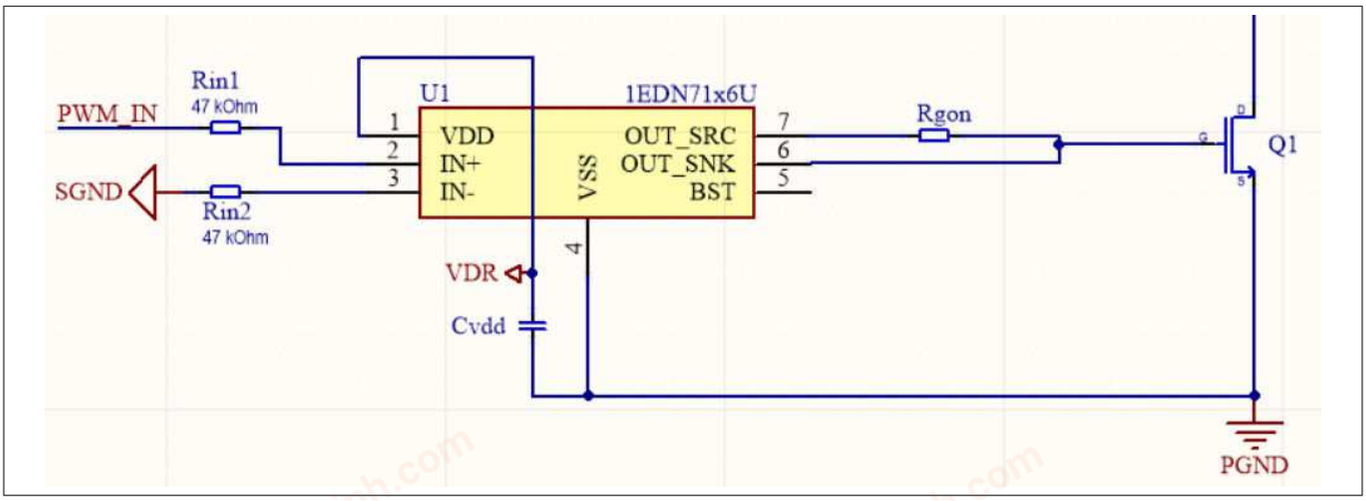


Figure 22 Single channel application circuit

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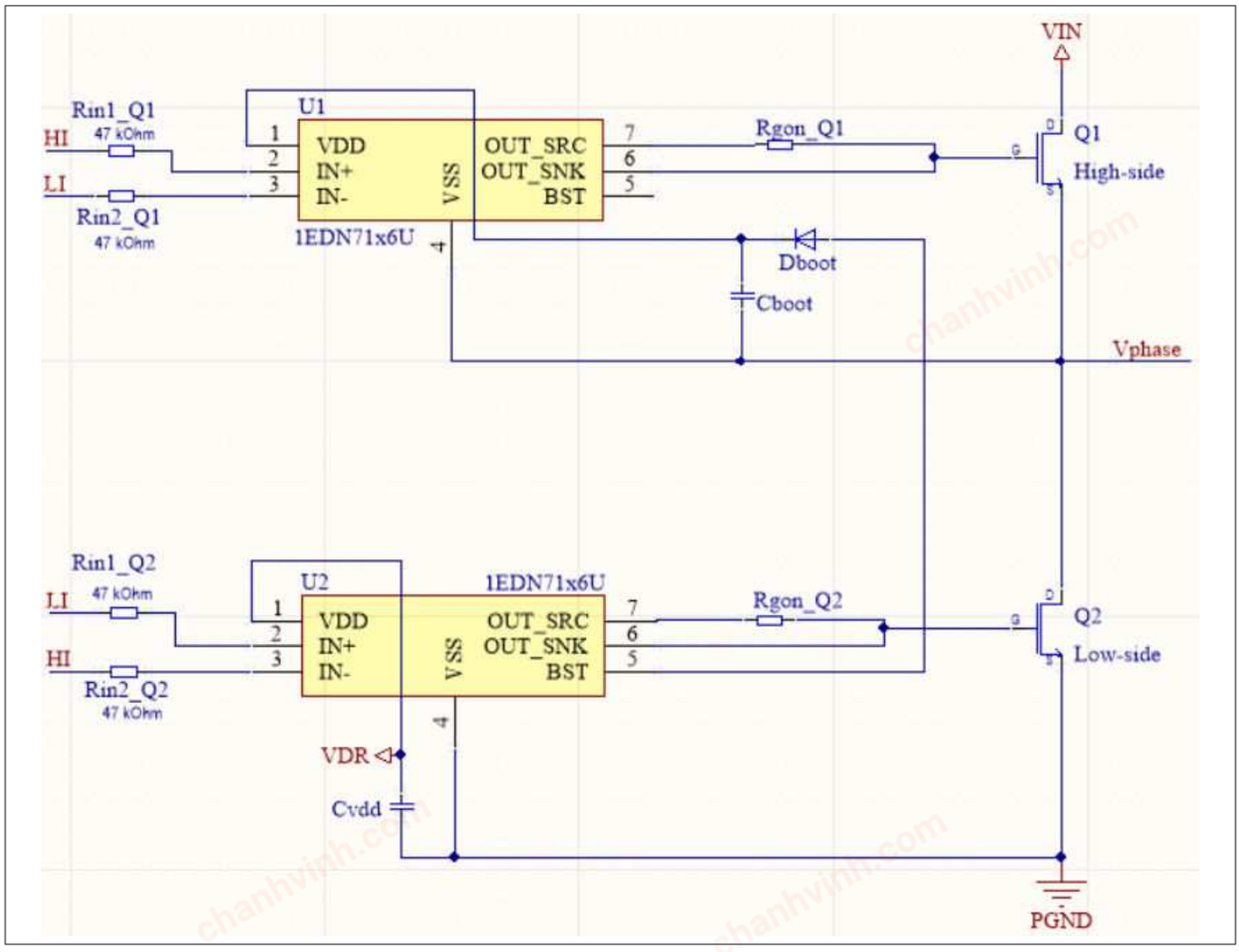


Figure 23 **Half-bridge with cross-connected signal inputs and active bootstrap clamping**

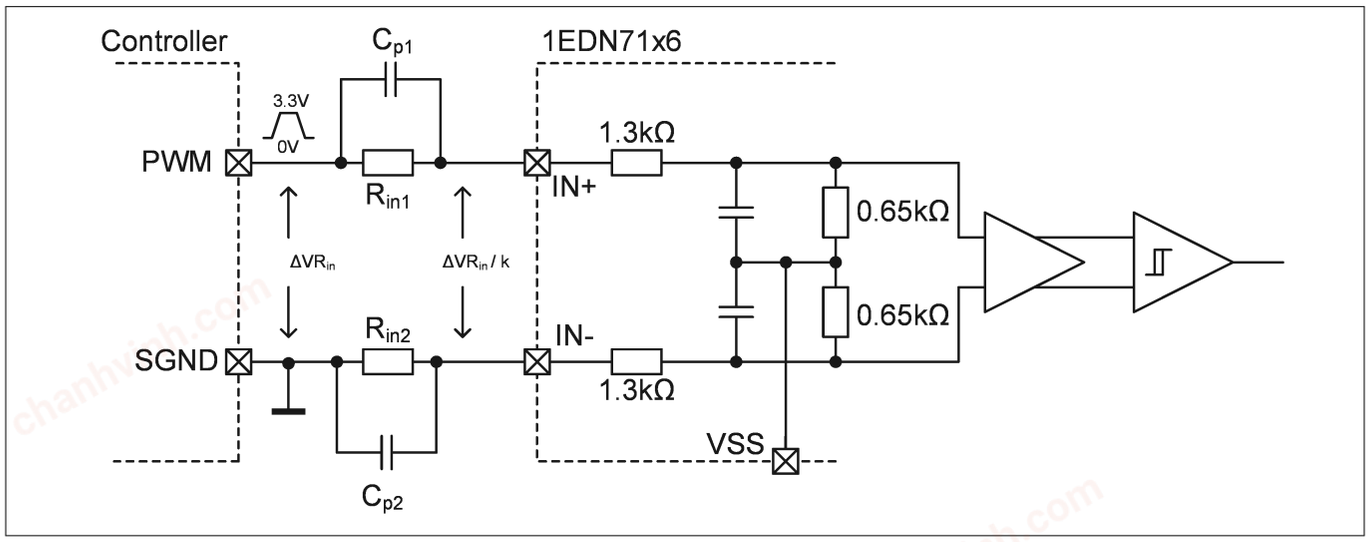


Figure 24 **TDI application circuit, including input external resistors and stray capacitance**

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5.2 Selection of TDI input resistors

The 1EDN71X6U requires precise input resistors at the IN+ and IN- pins, with resistance values of 47 kΩ or 75 kΩ, depending on the voltage level of the input logic signals. The driver is compatible with either a 3.3 V or a 5 V logic. These resistors are not optional, even if the application does not require the TDI function (for example low-side applications with no ground bounce concerns). The input logic thresholds at the IN+ and IN- pins are designed to be paired with the specified input resistor values. These input resistors should be selected with a 0.1% tolerance, especially in high-side applications, where the common-mode voltage rating is contingent upon tight matching of R_{IN1} and R_{IN1}. Extra care should be taken to ensure that these resistors are symmetrical, so that stray capacitance across them is also tightly matched. Figure 24 shows an example of how stray capacitances C_{p1} and C_{p2} could interfere with the symmetry and matching of R_{IN1} and R_{IN2}. To optimize this symmetry, the two resistors should have identical part numbers with the same package and footprint. Further PCB layout recommendations for ensuring symmetry are given later.

In high-side applications, the input resistors must also be rated for the power dissipation expected in the worst-case operating conditions. The common-mode voltage observed by the high-side transistor is "blocked" by each input resistor, so that the 1EDN71X6U is not exposed to the high voltage. The resistors dissipate power during the intervals where CM voltage is high, typically during the high-side transistor's duty ratio of each switching period. The power rating of the resistors should therefore be selected based on

$$P_{Rin1} = P_{Rin2} = \frac{V_{dc,max}{}^2}{R_{in1}} \times D$$

Equation 1

where:

P_{Rin1} = Required power rating for R_{in1}

P_{Rin2} = Required power rating for R_{in2}

D = High-side duty ratio

$V_{dc,max}$ = Maximum expected dc bus voltage, experienced as CM voltage during the high-side duty ratio

It is important to consider that the duty ratio may not be constant, so D should be selected as the duty ratio when operating at the maximum dc bus voltage.

The table below lists some examples for selecting the input resistors, based on logic voltage level, expected dc bus voltage, and duty ratio. For most applications, the power requirement is quite low, thereby allowing the designer to select very small resistor packages such as 0402 or 0603. In some extreme scenarios with a high dc voltage and high duty ratio simultaneously, larger packages with higher power ratings may be needed.

Table 10 Examples for selected input resistors

Maximum dc bus voltage	Logic voltage	Duty ratio	TDI input resistance	Resistor tolerance	Minimum Rin power rating
60 V	3.3 V	0.25	47 kΩ	0.1%	0.02 W
60 V	5 V	0.25	75 kΩ	0.1%	0.01 W
80 V	3.3 V	0.75	47 kΩ	0.1%	0.10 W
80 V	5 V	0.75	75 kΩ	0.1%	0.06 W

5.3 Selection of VDD bypass capacitor

The VDD bypass capacitor provides the gate charge to drive the transistor, as well as additional power consumption by the driver itself. It should be placed as close as possible to the VDD and VSS pins of the gate driver, which may require a particular footprint size for most applications.

The minimum value for this bypass capacitor can be calculated based on the maximum allowable voltage ripple in the design. This ripple should be minimized such that the lowest possible VDD is above the UVLO limit of the gate driver as well as above the safe driving voltage of the transistor. The charge dissipated per

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switching event is approximately equal to the driven transistor's gate charge. The minimum value can therefore be calculated as

$$C_{\mathrm{Vdd}} \gg \frac{\mathrm{Q_G}}{\Delta \mathrm{V_{DD,\,max}}}$$

Equation 2

In a half-bridge configuration, the VDD bypass capacitor also provides the charge for the bootstrap capacitor during the charging period. Therefore, the VDD bypass capacitor should be sized to be much larger than the bootstrap capacitor. The minimum value should be calculated as

$$C_{\mathrm{Vdd}} \gg \frac{\mathrm{Q_G} + \mathrm{Q_{BOOT}}}{\Delta \mathrm{V_{DD,\,max}}}$$

Equation 3

where QBOOT is the charge consumed by the bootstrapping circuit each cycle. This value is calculated in a later section.

In practice, this capacitance value should be increased somewhat to account for dc bias effects in the capacitor and other non-idealities in the circuit.

5.4 Selection of external bootstrap diode

When used in a half-bridge configuration, a bootstrapping circuit is often used to supply the high-side driver's V_{DD}. A fast recovery or schottky diode with low forward voltage drop is recommended in order to minimize the losses and leakage current. It should be chosen such that it can handle the peak transient current during start-up conditions and the blocking voltage rating should be higher than the maximum input voltage (V_{IN}) with added margin. It is important to consider that the output capacitance and reverse recovery of this bootstrap diode contributes to the total switch-node capacitance of the half-bridge, thereby increasing the total switching losses of the application circuit. A schottky diode with low output capacitance is therefore the best choice for most applications.

The 1EDN71x6U gate driver provides two options for bootstrap diode connection. The conventional approach is to connect the anode of the diode to the low-side V_{DD} rail, often with a current-limiting resistor between them to limit surge current during startup. However, the recommended approach with 1EDN71x6U is to connect the anode of the bootstrap diode to the BST pin of the low-side driver as shown in Figure 4 . This enables the integrated bootstrap clamping function of the driver, and it also provides current-limiting at startup without the need for an added resistor.

5.5 Selection of bootstrap capacitor

The bootstrap capacitor provides the necessary charge to drive the high-side transistor. It must be sized in such a way that its lowest voltage will be much higher than the UVLO threshold as well as above the minimum safe driving voltage of the transistor, during transient and normal operations.

To determine the minimum required bootstrap capacitance, the maximum allowable ripple in V_{BOOT} must be calculated as follows.

$$\Delta \mathrm{V_{BOOT,\,max}} = V_{\mathrm{DD}} - V_{\mathrm{F}} - V_{\mathrm{BOOT,\,min}}$$

Equation 4

where:

V_{DD} = Low-side gate driver supply voltage

V_F = Bootstrap diode forward voltage drop

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$V_{BOOT,min}$ is the minimum allowable voltage for the bootstrap capacitor, including transient events. This voltage must be at least high enough to avoid UVLO shutdown, as given by:

$$V_{BOOT,\,min} \geq V_{HBR} + V_{HBH}$$

Equation 5

where:

V_{HBR} = High-side driver UVLO rising threshold

V_{HBH} = High-side driver UVLO threshold hysteresis

However, the driven transistor may require a higher voltage than this UVLO minimum, in order to remain fully on and avoid linear-mode operation. If the calculated minimum V_{BOOT} is lower than the safe driving voltage of the transistor, then $V_{BOOT,min}$ should be increased accordingly.

Next, determine the total charge (Q_{BOOT}) that must be delivered by the bootstrap capacitor at maximum duty cycle. There are several factors that contribute to the discharge of the bootstrap capacitor such as the high-side transistor's total gate charge and gate-source leakage current, bootstrap diode reverse bias leakage current, and bootstrap capacitor leakage current. For the sake of simplicity, the bootstrap capacitor leakage current can typically be neglected. The total bootstrap charge can be estimated as follows:

$$Q_{BOOT} \approx Q_G + \frac{I_{Vdd} + (I_{diode} \times D_{max})}{f_{sw}}$$

Equation 6

where:

Q_G = High-side transistor total gate charge

I_{Vdd} = High-side driver maximum quiescent current

I_{diode} = Bootstrap diode reverse bias leakage current

D_{max} = Maximum high-side duty cycle

f_{sw} = Switching frequency

The minimum bootstrap capacitor value can then be calculated using the formula:

$$C_{BOOT} \gg \frac{Q_{BOOT}}{\Delta V_{BOOT,\,max}}$$

Equation 7

In practice, this capacitance value should be increased somewhat to account for dc bias effects in the capacitor and other non-idealities in the circuit.

5.6 Selection of external gate resistors

The turn-on and turn-off external gate resistors control the turn-on and turn-off current of the gate driver providing an external way to control the switching speed of the MOSFET for purposes such as voltage overshoot control, ringing reduction, EMI mitigation, spurious turn-on protection, shoot –through protection, etc. In most designs, no external gate resistor is needed. Each of the four product variants offers a different pull-up and pull-down resistance, along with a corresponding peak source and sink current. However, in cases where the designers prefers a different source and sink driving strength, an external gate resistor may be used.

The following formulas show the effect of the external gate resistor to the output current capability of the gate driver.

$$I_{SRC,\,PK} \leq \frac{V_{DD}}{R_{PU} + R_{G,\,int} + R_{Gon,\,ext}}$$

Equation 8

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$$I_{SNK,PK} \leq \frac{V_{DD}}{R_{PD} + R_{G,int} + R_{Goff,ext}}$$

Equation 9

where:

$I_{SRC,PK}$ = Peak source current

$I_{SNK,PK}$ = Peak sink current

R_{PU} = Gate driver pull-up resistance

R_{PD} = Gate driver pull-down resistance

V_{DD} = Gate driver supply voltage (equivalent to V_{BOOT} for high-side transistor)

$R_{G,int}$ = Internal gate resistance of driven transistor

$R_{Gon,ext}$ = External gate resistance connected between Source output and gate

$R_{Goff,ext}$ = External gate resistance connected between Sink output and gate

It is important to consider that the peak current may not reach this level during a fast switching transition, as is typical with GaN transistors. It is also worth nothing that this peak current cannot exceed the specified peak source/sink current of the gate driver, as the pull-up and pull-down transistors within the driver saturate at that current. However, the selection of product variant according to pull-up and pull-down resistance provides a close approximation to selection of external gate resistance in most cases.

Use of a non-zero R_{Goff_ext} is not recommended for most designs, as this limits the effectiveness of the active Miller clamp feature. It is therefore preferable to choose the product variant based on the desired sinking or pull-down strength, and then add R_{Gon_ext} only if needed to optimize the design.

5.7 PCB layout recommendations

The combination of the gate driver, bypass capacitors, and driven transistor forms a high-frequency current loop that defines the parasitic inductance in series with that loop. Likewise, in a half-bridge, the combination of the high-side and low-side transistors forms a high-frequency current loop with the bypass capacitors for the dc bus (for example Vin for a buck converter). The relative location on the PCB of those components is essential to reach high level of performance. The parasitic inductances within these loops can cause serious efficiency degradation due to dynamic effects. In addition, any coupling between the gate driving loops and half-bridge power loop can cause spurious switching events or other performance degradation. Coupling between either of these loops and the signal paths feeding to the TDI input resistors can also cause spurious switching. Finally, as mentioned previously, the TDI input circuit may be affected by stray capacitance and other asymmetries in the PCB design. Careful layout can help minimize or eliminate such unwanted effects.

The following recommendations help the designer to optimize the PCB layout, as demonstrated in the half-bridge example pictures below.

1. Keep all high-frequency loops as short as possible, and use differential returns for current paths to cancel the magnetic fields and reduce parasitic inductance.
2. Minimize stray inductance, especially on low impedance lines. All high-current traces (VDD, VSS, OUT_SRC, OUT_SNK) should be short and wide, and copper pours are recommended over traces when the design allows.
3. To optimize heat spreading, electrical shielding, and magnetic field cancellation, a VSS-connected copper pour should be placed directly underneath the IC as well as all components encompassed by the gate driving loop (for example bypass capacitors, gate and source pads of transistor). For the low-side driver, this shielding pour should be connected to PGND. For the high-side driver, it should be connected to the switch-node, which is the mid-point of the half-bridge.
4. To avoid interference between the power loop and gate loops, separate shielding layers should be used for each loop, even if they are both connected to the same net.
5. To optimize the symmetry of the TDI input resistors, they should be placed directly beside each other and symmetrically shielded on the first inner layer. The controller-side of the two resistors should be

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shielded by the controller ground net (SGND), and the driver-side of the two resistors should be shielded by the same VSS-connected copper used to shield the rest of the driving circuit.

6. The dielectric spacing between the top copper layer and first inner layer should be minimized to enhance the magnetic field cancellation effects. A spacing of 80 ~ 100 microns is used in the example below.

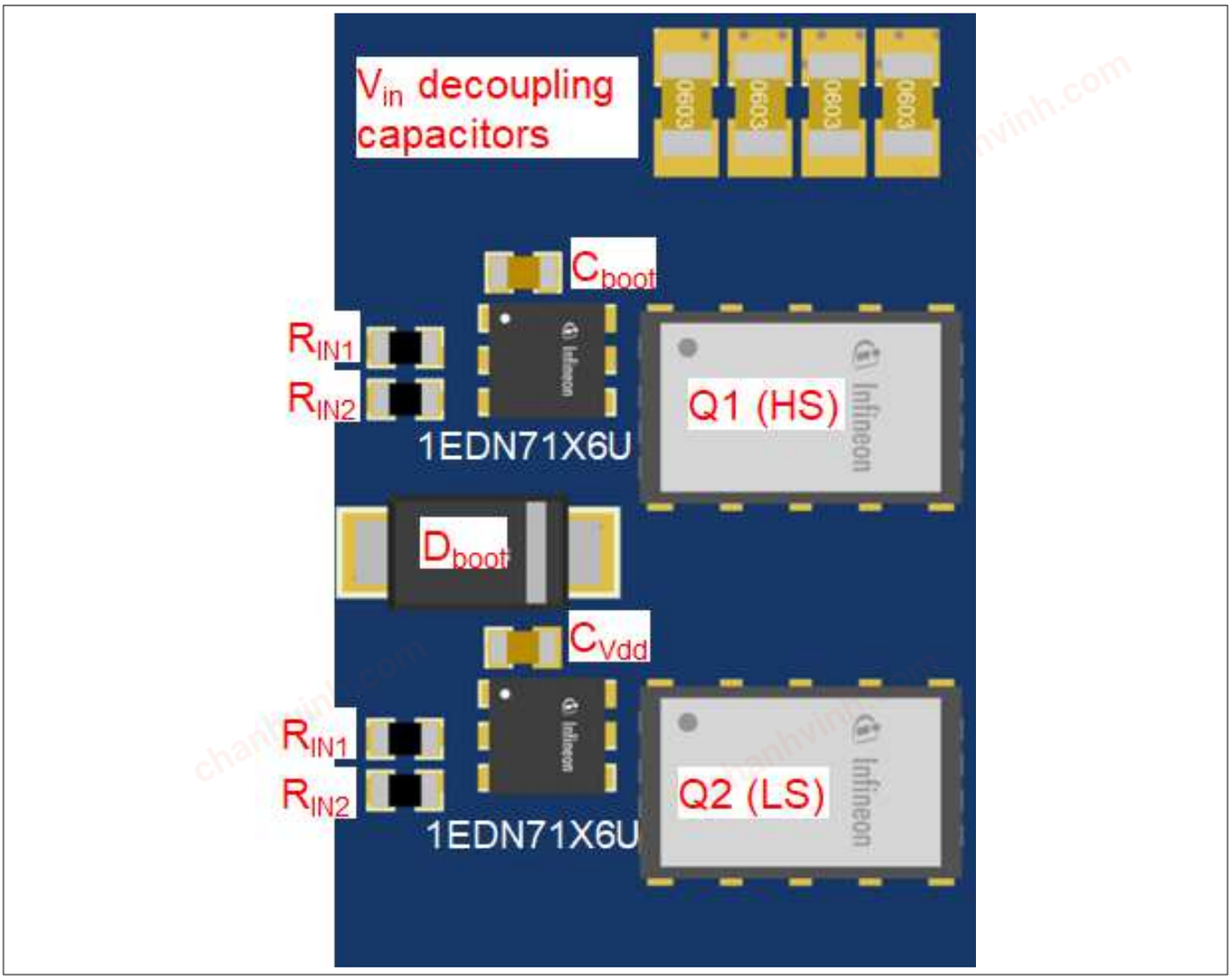


Figure 25 3D top-side view of example half-bridge implementation

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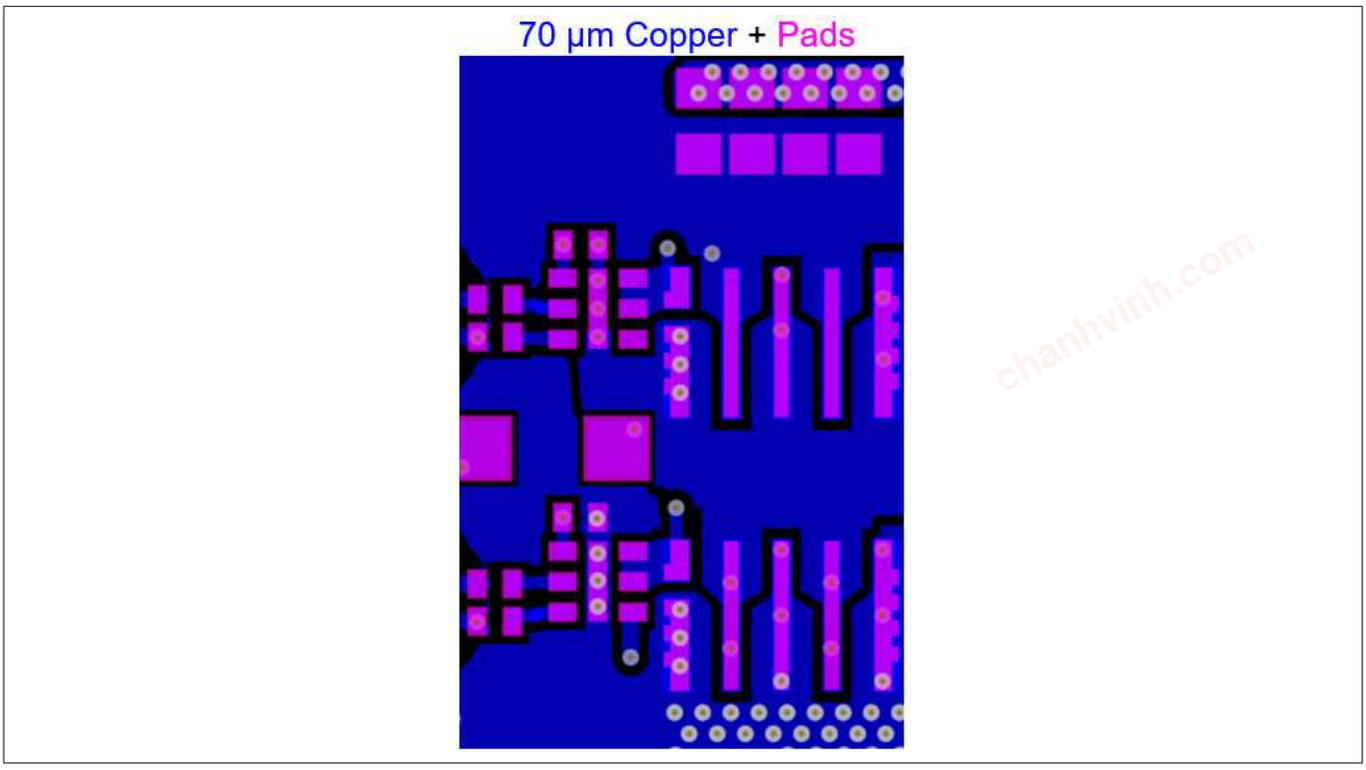


Figure 26 **Top copper layer of example half-bridge implementation**

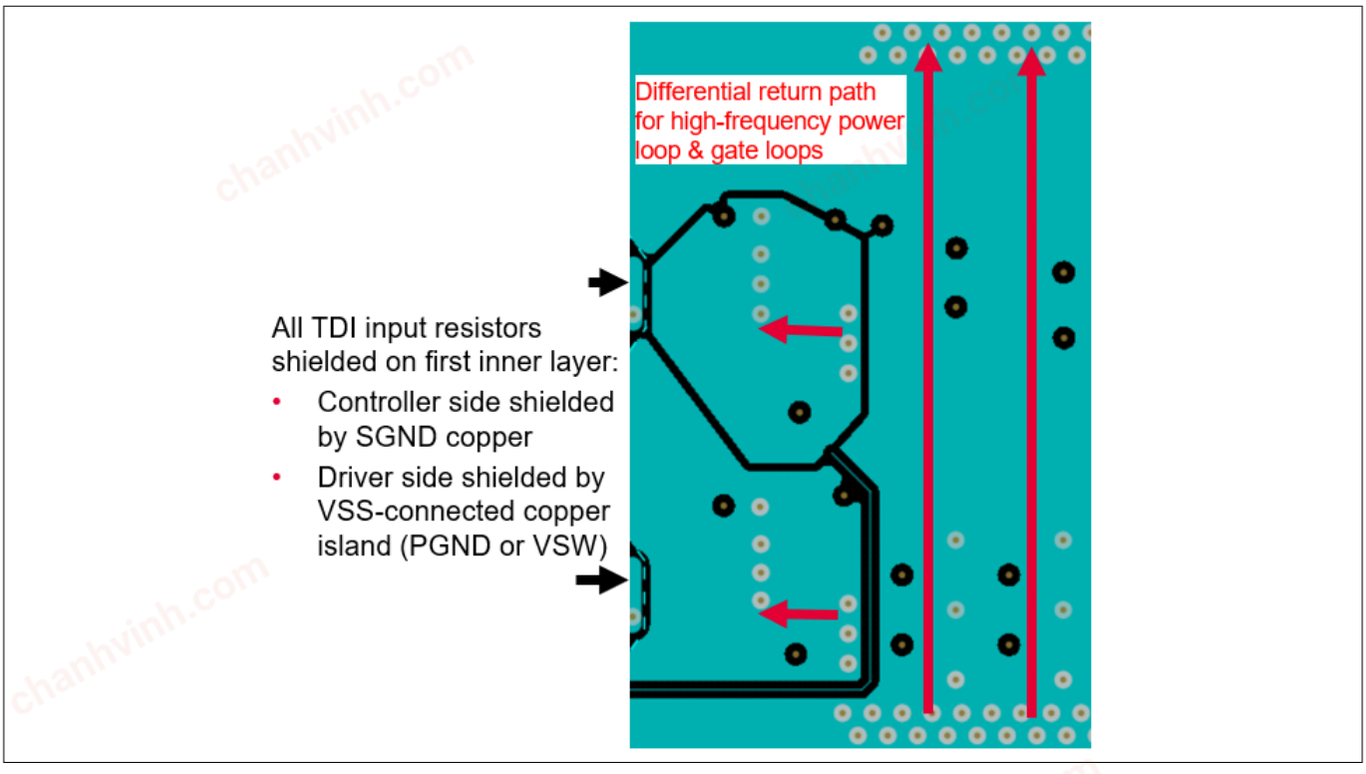


Figure 27 **First inner layer of example half-bridge implementation, separated from top layer by 80~100 µm dielectric**

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6 Package information

Base part number	Package type	From	Quantity	Orderable part number	Marking code
1EDN7116U	PG-TSNP-7-11	Tape and reel	4500	1EDN7116UXTSA1	1EDN7116U
1EDN7126U	PG-TSNP-7-11	Tape and reel	4500	1EDN7126UXTSA1	1EDN7126U
1EDN7136U	PG-TSNP-7-11	Tape and reel	4500	1EDN7136UXTSA1	1EDN7136U
1EDN7146U	PG-TSNP-7-11	Tape and reel	4500	1EDN7146UXTSA1	1EDN7146U

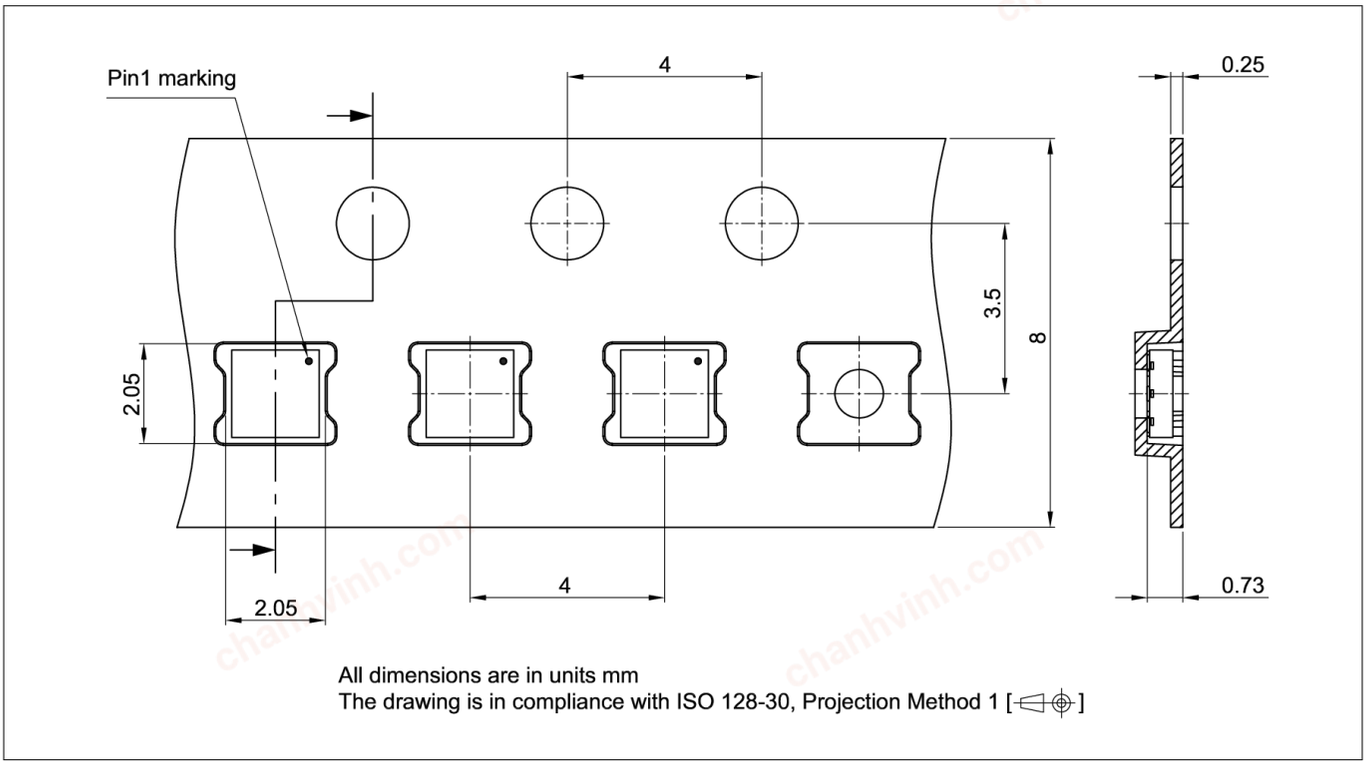


Figure 28 PG-TSNP-7-11 packaging

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6 Package information

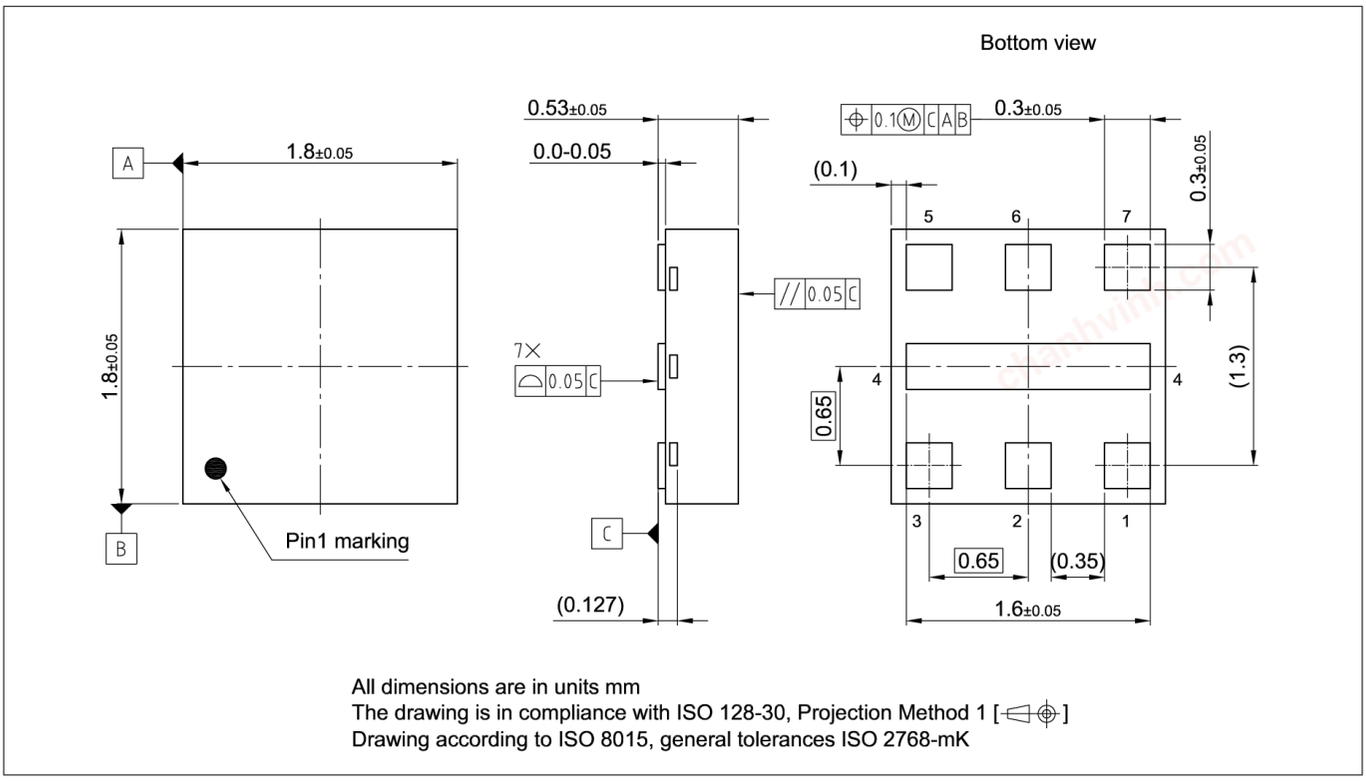


Figure 29 PG-TSNP-7-11 package dimensions

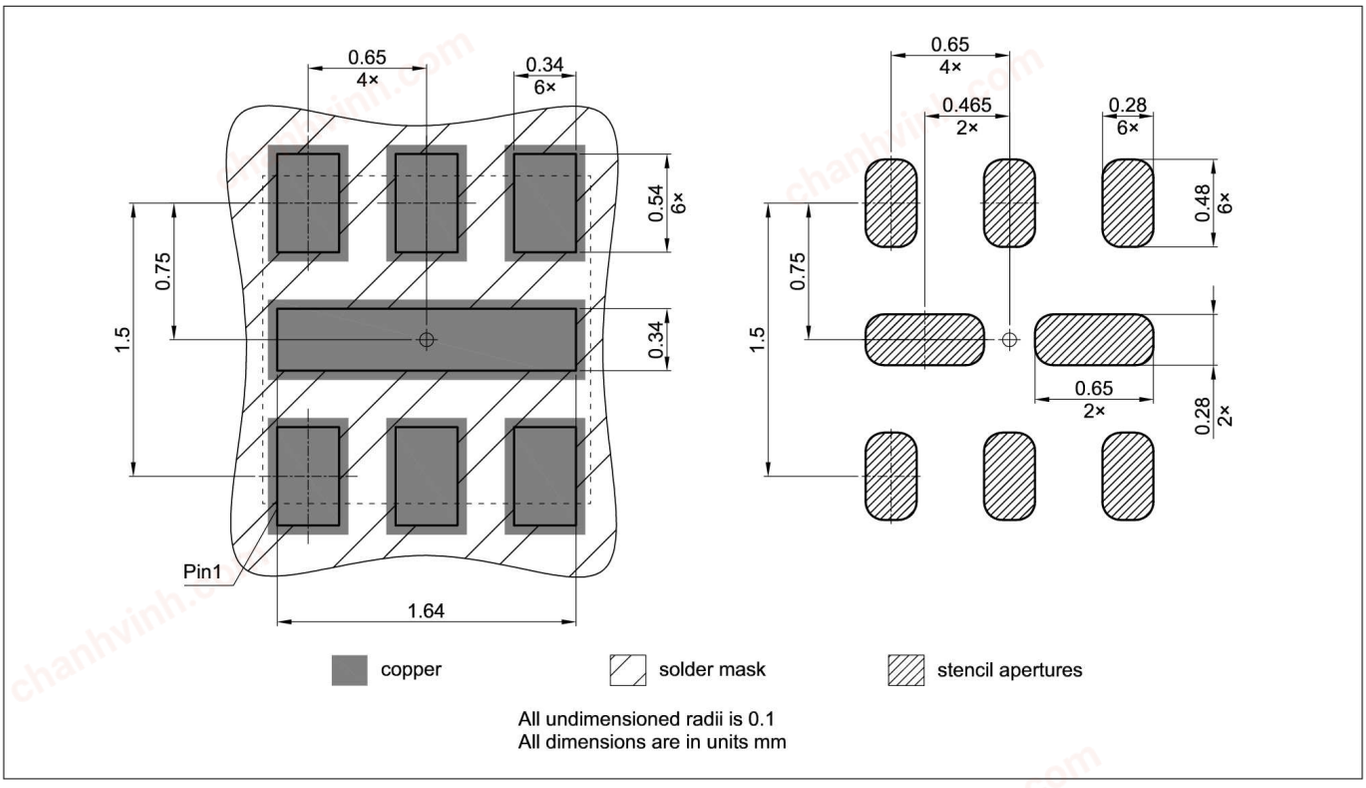


Figure 30 PG-TSNP-7-11 recommended landing pattern

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Revision History

1EDN71x6U

Revision: 2022-07-29, Rev. 2.0

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2022-07-29	Release of final version

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